

M85 Hardware Design

GSM/GPRS Module Series

Rev. M85_Hardware_Design_V3.0

Date: 2015-10-22



Our aim is to provide customers with timely and comprehensive service. For any assistance, please contact our company headquarters:

Quectel Wireless Solutions Co., Ltd.

Office 501, Building 13, No.99, Tianzhou Road, Shanghai, China, 200233

Tel: +86 21 5108 6236

Mail: info@quectel.com

Or our local office, for more information, please visit:

<http://www.quectel.com/support/salesupport.aspx>

For technical support, to report documentation errors, please visit:

<http://www.quectel.com/support/techsupport.aspx>

Or Email: Support@quectel.com

GENERAL NOTES

QUECTEL OFFERS THIS INFORMATION AS A SERVICE TO ITS CUSTOMERS. THE INFORMATION PROVIDED IS BASED UPON CUSTOMERS' REQUIREMENTS. QUECTEL MAKES EVERY EFFORT TO ENSURE THE QUALITY OF THE INFORMATION IT MAKES AVAILABLE. QUECTEL DOES NOT MAKE ANY WARRANTY AS TO THE INFORMATION CONTAINED HEREIN, AND DOES NOT ACCEPT ANY LIABILITY FOR ANY INJURY, LOSS OR DAMAGE OF ANY KIND INCURRED BY USE OF OR RELIANCE UPON THE INFORMATION. ALL INFORMATION SUPPLIED HEREIN IS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE.

COPYRIGHT

THIS INFORMATION CONTAINED HERE IS PROPRIETARY TECHNICAL INFORMATION OF QUECTEL CO., LTD. TRANSMITTABLE, REPRODUCTION, DISSEMINATION AND EDITING OF THIS DOCUMENT AS WELL AS UTILIZATION OF THIS CONTENTS ARE FORBIDDEN WITHOUT PERMISSION. OFFENDERS WILL BE HELD LIABLE FOR PAYMENT OF DAMAGES. ALL RIGHTS ARE RESERVED IN THE EVENT OF A PATENT GRANT OR REGISTRATION OF A UTILITY MODEL OR DESIGN.

Copyright © Quectel Wireless Solutions Co., Ltd. 2015. All rights reserved.

About the Document

History

Revision	Date	Author	Description
1.0	2012-07-15	Winter CHEN	Initial
1.1	2013-11-04	Felix YIN	Optimized the parameters of VBAT ripple in Table 33
3.0	2015-03-13	Stone YU/ Hollis WANG	<ol style="list-style-type: none">1. Updated module key features in Table 12. Modified pin assignment in Figure 23. Updated DC characteristics of module's pins in Table 44. Updated reference circuit for power supply in Figure 55. Modified over-voltage or under-voltage automatic shutdown in Section 3.4.2.36. Modified RTC backup in Section 3.67. Modified UART application in Section 3.7.48. Deleted the data call mode in Section 3.139. Added antenna requirement in Section 4.5

Contents

About the Document	2
Contents	3
Table Index	6
Figure Index	7
1 Introduction	9
1.1. Safety Information	10
2 Product Concept	11
2.1. General Description.....	11
2.2. Directives and Standards	11
2.2.1. FCC Statement.....	11
2.2.2. FCC Radiation Exposure Statement.....	12
2.3. Key Features	12
2.4. Functional Diagram	14
2.5. Evaluation Board	15
3 Application Interface	16
3.1. Pin of Module.....	17
3.1.1. Pin Assignment	17
3.1.2. Pin Description	18
3.2. Operating Modes.....	23
3.3. Power Supply	24
3.3.1. Power Features of Module.....	24
3.3.2. Decrease Supply Voltage Drop.....	24
3.3.3. Reference Design For Power Supply	25
3.3.4. Monitor Power Supply	26
3.4. Power On and Down Scenarios.....	26
3.4.1. Power On	26
3.4.2. Power Down	28
3.4.2.1. Power Down Module Using the PWRKEY Pin.....	28
3.4.2.2. Power Down Module Using AT Command	29
3.4.2.3. Over-voltage or Under-voltage Automatic Shutdown.....	29
3.4.2.4. Emergency Shutdown Using EMERG_OFF Pin	30
3.4.3. Restart.....	31
3.5. Power Saving	32
3.5.1. Minimum Functionality Mode	32
3.5.2. SLEEP Mode.....	33
3.5.3. Wake up Module from SLEEP Mode	33
3.5.4. Summary of State Transition.....	33
3.6. RTC Backup	34

3.7.	Serial Interfaces.....	36
3.7.1.	UART Port	38
3.7.1.1.	The Features of UART Port.....	38
3.7.1.2.	The Connection of UART Port.....	39
3.7.1.3.	Firmware Upgrade.....	40
3.7.2.	Debug Port	41
3.7.3.	Auxiliary UART Port	42
3.7.4.	UART Application	42
3.8.	Audio Interfaces.....	44
3.8.1.	Decrease TDD Noise and Other Noise.....	45
3.8.2.	Microphone Interfaces Design	46
3.8.3.	Receiver and Speaker Interface Design	46
3.8.4.	Earphone Interface Design	48
3.8.5.	Loud Speaker Interface Design.....	49
3.8.6.	Audio Characteristics	49
3.9.	SIM Card Interfaces	50
3.10.	SD Card Interface.....	53
3.11.	PCM Interface.....	55
3.11.1.	Configuration.....	56
3.11.2.	Timing.....	56
3.11.3.	Reference Design	58
3.11.4.	AT Command	58
3.12.	ADC	59
3.13.	Behaviors Of The RI	60
3.14.	Network Status Indication.....	62
3.15.	Operating Status Indication	62
4	Antenna Interface.....	64
4.1.	Reference Design.....	64
4.2.	RF Output Power.....	65
4.3.	RF Receiving Sensitivity.....	65
4.4.	Operating Frequencies.....	66
4.5.	Antenna Requirement	66
4.6.	RF Cable Soldering	67
5	Electrical, Reliability and Radio Characteristics	68
5.1.	Absolute Maximum Ratings.....	68
5.2.	Operating Temperature	69
5.3.	Power Supply Ratings	69
5.4.	Current Consumption	70
5.5.	Electro-static Discharge	72
6	Mechanical Dimensions	74
6.1.	Mechanical Dimensions of Module	74
6.2.	Recommended Footprint.....	76
6.3.	Top View of the Module	77

6.4.	Bottom View of the Module	77
7	Storage and Manufacturing	78
7.1.	Storage	78
7.2.	Soldering	79
7.3.	Packaging.....	80
8	Appendix A Reference.....	82
9	Appendix B GPRS Coding Scheme	87
10	Appendix C GPRS Multi-slot Class.....	89

Table Index

TABLE 1: MODULE KEY FEATURES	12
TABLE 2: CODING SCHEMES AND MAXIMUM NET DATA RATES OVER AIR INTERFACE	14
TABLE 3: PIN DESCRIPTION	18
TABLE 4: OVERVIEW OF OPERATING MODES	23
TABLE 5: SUMMARY OF STATE TRANSITION	33
TABLE 6: LOGIC LEVELS OF THE UART INTERFACE	37
TABLE 7: PIN DEFINITION OF THE UART INTERFACES	37
TABLE 8: PIN DEFINITION OF AUDIO INTERFACE	44
TABLE 9: AOUT3 OUTPUT CHARACTERISTICS	45
TABLE 10: TYPICAL ELECTRET MICROPHONE CHARACTERISTICS	49
TABLE 11: TYPICAL SPEAKER CHARACTERISTICS	49
TABLE 12: PIN DEFINITION OF THE SIM INTERFACE	50
TABLE 13: PIN DEFINITION OF THE SD CARD INTERFACE	54
TABLE 14: PIN DEFINITION OF THE SD CARD INTERFACE	54
TABLE 15: PIN DEFINITION OF PCM INTERFACE	55
TABLE 16: CONFIGURATION	56
TABLE 17: QPCMON COMMAND DESCRIPTION	59
TABLE 18: QPCMVOL COMMAND DESCRIPTION	59
TABLE 19: PIN DEFINITION OF THE ADC	60
TABLE 20: CHARACTERISTICS OF THE ADC	60
TABLE 21: BEHAVIORS OF THE RI	60
TABLE 22: WORKING STATE OF THE NETLIGHT	62
TABLE 23: PIN DEFINITION OF THE STATUS	63
TABLE 24: PIN DEFINITION OF THE RF_ANT	64
TABLE 25: THE MODULE CONDUCTED RF OUTPUT POWER	65
TABLE 26: THE MODULE CONDUCTED RF RECEIVING SENSITIVITY	65
TABLE 27: THE MODULE OPERATING FREQUENCIES	66
TABLE 28: ANTENNA CABLE REQUIREMENTS	66
TABLE 29: ANTENNA REQUIREMENTS	66
TABLE 30: ABSOLUTE MAXIMUM RATINGS	68
TABLE 31: OPERATING TEMPERATURE	69
TABLE 32: THE MODULE POWER SUPPLY RATINGS	69
TABLE 33: THE MODULE CURRENT CONSUMPTION	70
TABLE 34: THE ESD ENDURANCE (TEMPERATURE: 25°C, HUMIDITY: 45%)	73
TABLE 35: REEL PACKING	81
TABLE 36: RELATED DOCUMENTS	82
TABLE 37: TERMS AND ABBREVIATIONS	83
TABLE 38: DESCRIPTION OF DIFFERENT CODING SCHEMES	87
TABLE 39: GPRS MULTI-SLOT CLASSES	89

Figure Index

FIGURE 1: MODULE FUNCTIONAL DIAGRAM.....	15
FIGURE 2: PIN ASSIGNMENT	17
FIGURE 3: VOLTAGE RIPPLE DURING TRANSMITTING	24
FIGURE 4: REFERENCE CIRCUIT FOR THE VBAT INPUT	25
FIGURE 5: REFERENCE CIRCUIT FOR POWER SUPPLY	25
FIGURE 6: TURN ON THE MODULE WITH AN OPEN-COLLECTOR DRIVER.....	26
FIGURE 7: TURN ON THE MODULE WITH A BUTTON	27
FIGURE 8: TURN-ON TIMING	27
FIGURE 9: TURN-OFF TIMING	28
FIGURE 10: AN OPEN-COLLECTOR DRIVER FOR EMERG_OFF	30
FIGURE 11: REFERENCE CIRCUIT FOR EMERG_OFF BY USING BUTTON	31
FIGURE 12: TIMING OF RESTARTING SYSTEM.....	31
FIGURE 13: TIMING OF RESTARTING SYSTEM AFTER EMERGENCY SHUTDOWN	32
FIGURE 14: VRTC IS SUPPLIED BY A NON-CHARGEABLE BATTERY	35
FIGURE 15: VRTC IS SUPPLIED BY A RECHARGEABLE BATTERY	35
FIGURE 16: VRTC IS SUPPLIED BY A CAPACITOR	36
FIGURE 17: REFERENCE DESIGN FOR FULL-FUNCTION UART	39
FIGURE 18: REFERENCE DESIGN FOR UART PORT.....	40
FIGURE 19: REFERENCE DESIGN FOR UART PORT WITH HARDWARE FLOW CONTROL	40
FIGURE 20: REFERENCE DESIGN FOR FIRMWARE UPGRADE.....	41
FIGURE 21: REFERENCE DESIGN FOR DEBUG PORT	41
FIGURE 22: REFERENCE DESIGN FOR AUXILIARY UART PORT	42
FIGURE 23: LEVEL MATCH DESIGN FOR 3.3V SYSTEM.....	42
FIGURE 24: SKETCH MAP FOR RS-232 INTERFACE MATCH.....	43
FIGURE 25: REFERENCE DESIGN FOR AIN1&AIN2	46
FIGURE 26: HANDSET INTERFACE DESIGN FOR AOUT1	46
FIGURE 27: SPEAKER INTERFACE DESIGN WITH AN AMPLIFIER FOR AOUT1	47
FIGURE 28: HANDSET INTERFACE DESIGN FOR AOUT2	47
FIGURE 29: SPEAKER INTERFACE DESIGN WITH AN AMPLIFIER FOR AOUT2	48
FIGURE 30: EARPHONE INTERFACE DESIGN.....	48
FIGURE 31: LOUD SPEAKER INTERFACE DESIGN.....	49
FIGURE 32: REFERENCE CIRCUIT FOR SIM1 INTERFACE WITH 8-PIN SIM CARD HOLDER	51
FIGURE 33: REFERENCE CIRCUIT FOR SIM1 INTERFACE WITH THE 6-PIN SIM CARD HOLDER	52
FIGURE 34: REFERENCE CIRCUIT FOR SIM2 INTERFACE WITH THE 6-PIN SIM CARD HOLDER	52
FIGURE 35: REFERENCE CIRCUIT FOR SD CARD	54
FIGURE 36: LONG SYNCHRONIZATION & SIGN EXTENSION DIAGRAM.....	57
FIGURE 37: LONG SYNCHRONIZATION & ZERO PADDING DIAGRAM.....	57
FIGURE 38: SHORT SYNCHRONIZATION & SIGN EXTENSION DIAGRAM.....	57
FIGURE 39: SHORT SYNCHRONIZATION & ZERO PADDING DIAGRAM	58
FIGURE 40: REFERENCE DESIGN FOR PCM	58
FIGURE 41: RI BEHAVIOR OF VOICE CALLING AS A RECEIVER	61
FIGURE 42: RI BEHAVIOR AS A CALLER	61

FIGURE 43: RI BEHAVIOR OF URC OR SMS RECEIVED 61
FIGURE 44: REFERENCE DESIGN FOR NETLIGHT 62
FIGURE 45: REFERENCE DESIGN FOR STATUS..... 63
FIGURE 46: REFERENCE DESIGN FOR RF 64
FIGURE 47: RF SOLDERING SAMPLE 67
FIGURE 48: M85 MODULE TOP AND SIDE DIMENSIONS (UNIT: MM) 74
FIGURE 49: M85 MODULE BOTTOM DIMENSIONS (UNIT: MM)..... 75
FIGURE 50: THE PAD DIMENSIONS (UNIT: MM) 75
FIGURE 51: RECOMMENDED FOOTPRINT (UNIT: MM)..... 76
FIGURE 52: TOP VIEW OF THE MODULE 77
FIGURE 53: BOTTOM VIEW OF THE MODULE..... 77
FIGURE 54: RAMP-SOAK-SPIKE REFLOW PROFILE..... 79
FIGURE 55: TAPE AND REEL INFORMATION 81
FIGURE 56: RADIO BLOCK STRUCTURE OF CS-1, CS-2 AND CS-3..... 87
FIGURE 57: RADIO BLOCK STRUCTURE OF CS-4..... 88

1 Introduction

This document defines the M85 module and describes its hardware interface which are connected with the customer application and the air interface.

This document can help you quickly understand module interface specifications, electrical and mechanical details. Associated with application notes and user guide, you can use M85 module to design and set up mobile applications easily.

1.1. Safety Information

The following safety precautions must be observed during all phases of the operation, such as usage, service or repair of any cellular terminal or mobile incorporating M85 module. Manufacturers of the cellular terminal should send the following safety information to users and operating personnel and to incorporate these guidelines into all manuals supplied with the product. If not so, Quectel does not take on any liability for customer failure to comply with these precautions.



Full attention must be given to driving at all times in order to reduce the risk of an accident. Using a mobile while driving (even with a handsfree kit) cause distraction and can lead to an accident. You must comply with laws and regulations restricting the use of wireless devices while driving.



Switch off the cellular terminal or mobile before boarding an aircraft. Make sure it switched off. The operation of wireless appliances in an aircraft is forbidden to prevent interference with communication systems. Consult the airline staff about the use of wireless devices on boarding the aircraft. If your device offers a Flight Mode which must be enabled prior to boarding an aircraft.



Switch off your wireless device when in hospitals or clinics or other health care facilities. These requests are desinged to prevent possible interference with sensitive medical equipment.



Cellular terminals or mobiles operate over radio frequency signal and cellular network and cannot be guaranteed to connect in all conditions, for example no mobile fee or an invalid SIM card. While you are in this condition and need emergent help, please remember using emergency call. In order to make or receive call, the cellular terminal or mobile must be switched on and in a service area with adequate cellular signal strength.



Your cellular terminal or mobile contains a transmitter and receiver. When it is ON , it receives and transmits radio frequency energy. RF interference can occur if it is used close to TV set, radio, computer or other electric equipment.



In locations with potentially explosive atmospheres, obey all posted signs to turn off wireless devices such as your phone or other cellular terminals. Areas with potentially expositive atmospheres including fuelling areas, below decks on boats, fuel or chemical transfer or storage facilities, areas where the air contains chemicals or particles such as grain, dust or metal powders.

2 Product Concept

2.1. General Description

M85 is a Quad-band GSM/GPRS engine that works at frequencies of GSM850MHz, EGSM900MHz, DCS1800MHz and PCS1900MHz. The M85 features GPRS multi-slot class 12 and supports the GPRS coding schemes CS-1, CS-2, CS-3 and CS-4. For more details about GPRS multi-slot classes and coding schemes, please refer to the **Appendix B & C**.

With a tiny profile of 24.5mm × 25.3mm × 2.6mm, the module can meet almost all the requirements for M2M applications, including Vehicles and Personal Tracking, Security System, Wireless POS, Industrial PDA, Smart Metering, and Remote Maintenance & Control, etc.

M85 is an SMD type module with LCC package, which can be easily embedded into applications. It provides abundant hardware interfaces like PCM and SD Card Interface.

Designed with power saving technique, the current consumption of M85 is as low as 1.3 mA in SLEEP mode when DRX is 5.

M85 is integrated with Internet service protocols, such as TCP/UDP, FTP and PPP. Extended AT commands have been developed for you to use these Internet service protocols easily.

The module fully complies with the RoHS directive of the European Union.

2.2. Directives and Standards

The M85 module is designed to comply with the FCC statements. **FCC ID: XMR201511M85**
The Host system using M85 should have label “contains FCC ID: XMR201511M85”.

2.2.1. FCC Statement

Changes or modifications not expressly approved by the party responsible for compliance could void the user’s authority to operate the equipment.

2.2.2. FCC Radiation Exposure Statement

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator and your body as well as kept minimum 20cm from radio antenna depending on the Mobile status of this module usage. This module should NOT be installed and operating simultaneously with other radio. The manual of the host system, which uses M85, must include RF exposure warning statement to advice user should keep minimum 20cm from the radio antenna of M85 module depending on the Mobile status. Note: If a portable device (such as PDA) uses M85 module, the device needs to do permissive change and SAR testing.

The following list indicates the performance of antenna gain in certificate testing.

Part Number	Frequency Range (MHz)	Peak Gain (XZ-V)	Average Gain(XZ-V)	VS WR	Impedance
3R007	GSM850:824~894MHz EGSM900:880~960MHz DCS1800:1710~1880MHz PCS1900: 1850~1990MHz	1 dBi typ.	1 dBi typ.	2 max	50Ω

2.3. Key Features

The following table describes the detailed features of M85 module.

Table 1: Module Key Features

Feature	Implementation
Power Supply	Single supply voltage: 3.3V~4.6V Typical supply voltage: 4.0V
Power Saving	Typical power consumption in SLEEP mode: 1.3 mA@ DRX=5 1.2 mA@ DRX=9
Frequency Bands	<ul style="list-style-type: none"> ● Quad-band: GSM850, EGSM900, DCS1800, PCS1900 ● The module can search these frequency bands automatically ● The frequency bands can be set by AT command ● Compliant to GSM Phase 2/2+
GSM Class	Small MS
Transmitting Power	<ul style="list-style-type: none"> ● Class 4 (2W) at GSM850 and EGSM900 ● Class 1 (1W) at DCS1800 and PCS1900

GPRS Connectivity	<ul style="list-style-type: none"> ● GPRS multi-slot class 12 (default) ● GPRS multi-slot class 1~12 (configurable) ● GPRS mobile station class B
DATA GPRS	<ul style="list-style-type: none"> ● GPRS data downlink transfer: max. 85.6kbps ● GPRS data uplink transfer: max. 85.6kbps ● Coding scheme: CS-1, CS-2, CS-3 and CS-4 ● Support the protocols PAP (Password Authentication Protocol) usually used for PPP connections ● Internet service protocols: TCP/UDP/FTP/PPP/HTTP/NTP/MMS/SMTP/PING ● Support Packet Broadcast Control Channel (PBCCH) ● Support Unstructured Supplementary Service Data (USSD)
Temperature Range	<ul style="list-style-type: none"> ● Normal operation: -35°C ~ +80°C ● Restricted operation: -40°C ~ -35°C and +80°C ~ +85°C ¹⁾ ● Storage temperature: -45°C ~ +90°C
SMS	<ul style="list-style-type: none"> ● Text and PDU mode ● SMS storage: SIM card
SIM Interfaces	Support SIM card: 1.8V, 3V
Audio Features	<p>Speech codec modes:</p> <ul style="list-style-type: none"> ● Half Rate (ETS 06.20) ● Full Rate (ETS 06.10) ● Enhanced Full Rate (ETS 06.50/06.60/06.80) ● Adaptive Multi-Rate (AMR) ● Echo Suppression ● Noise Reduction ● Embedded one amplifier of class AB with maximum driving power up to 870mW
UART Interfaces	<p>UART Port:</p> <ul style="list-style-type: none"> ● Seven lines on UART port interface ● Used for AT command, GPRS data ● Multiplexing function ● Support autobauding from 4800bps to 115200bps <p>Debug Port:</p> <ul style="list-style-type: none"> ● Two lines on debug port interface DBG_TXD and DBG_RXD ● Use for software debugging and log output <p>Auxiliary Port:</p> <ul style="list-style-type: none"> ● Used for AT command
Phonebook Management	Support phonebook types: SM, ME, ON, MC, RC, DC, LD, LA
SIM Application Toolkit	Support SAT class 3, GSM 11.14 Release 99
Real Time Clock	Supported

Physical Characteristics	Size: 25.3±0.15 × 24.5±0.15 × 2.6±0.2mm Weight: Approx. 3.3g
Firmware Upgrade	Firmware upgrade via UART Port
Antenna Interface	Connected to antenna pad with 50 Ohm impedance control

NOTE

¹⁾ When the module works within this temperature range, the deviations from the GSM specification may occur. For example, the frequency error or the phase error will be increased.

Table 2: Coding Schemes and Maximum Net Data Rates over Air Interface

Coding scheme	1 Timeslot	2 Timeslot	4 Timeslot
CS-1	9.05kbps	18.1kbps	36.2kbps
CS-2	13.4kbps	26.8kbps	53.6kbps
CS-3	15.6kbps	31.2kbps	62.4kbps
CS-4	21.4kbps	42.8kbps	85.6kbps

2.4. Functional Diagram

The following figure shows a block diagram of M85 and illustrates the major functional parts.

- Radio frequency part
- Serial Flash
- Power management
- The Peripheral interface
 - Power supply
 - Turn-on/off interface
 - UART interfaces
 - Audio interfaces
 - SIM interfaces
 - SD interface
 - PCM interface
 - ADC interface
 - RTC interface

—RF interface

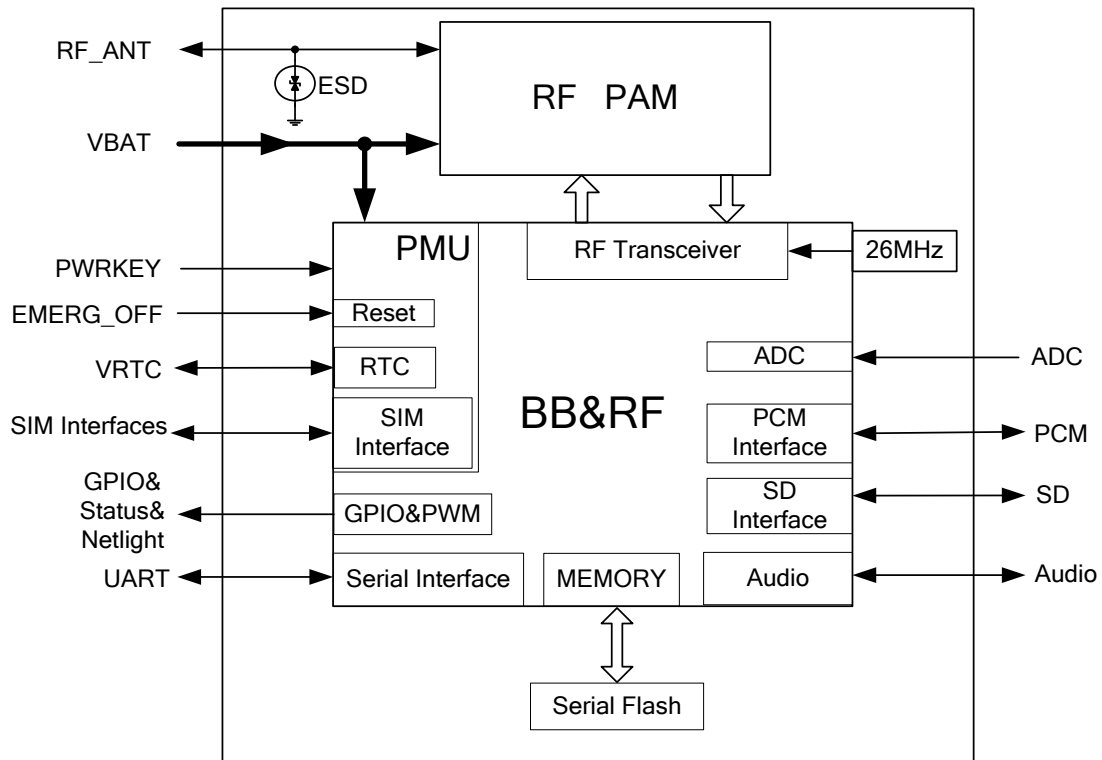


Figure 1: Module Functional Diagram

2.5. Evaluation Board

In order to help customer to develop applications with M85, Quectel supplies an evaluation board (EVB), RS-232 to USB cable, power adapter, earphone, antenna and other peripherals to control or test the module. For details, please refer to the *document [12]*.

3 Application Interface

The module adopts LCC package and has 83 pins. The following chapters provide detailed descriptions about these pins below.

- Power supply
- Power on/down
- Power saving
- RTC
- Serial interfaces
- Audio interfaces
- SIM interfaces
- SD interface
- PCM interface
- ADC
- RI
- NETLIGHT
- Status

3.1. Pin of Module

3.1.1. Pin Assignment

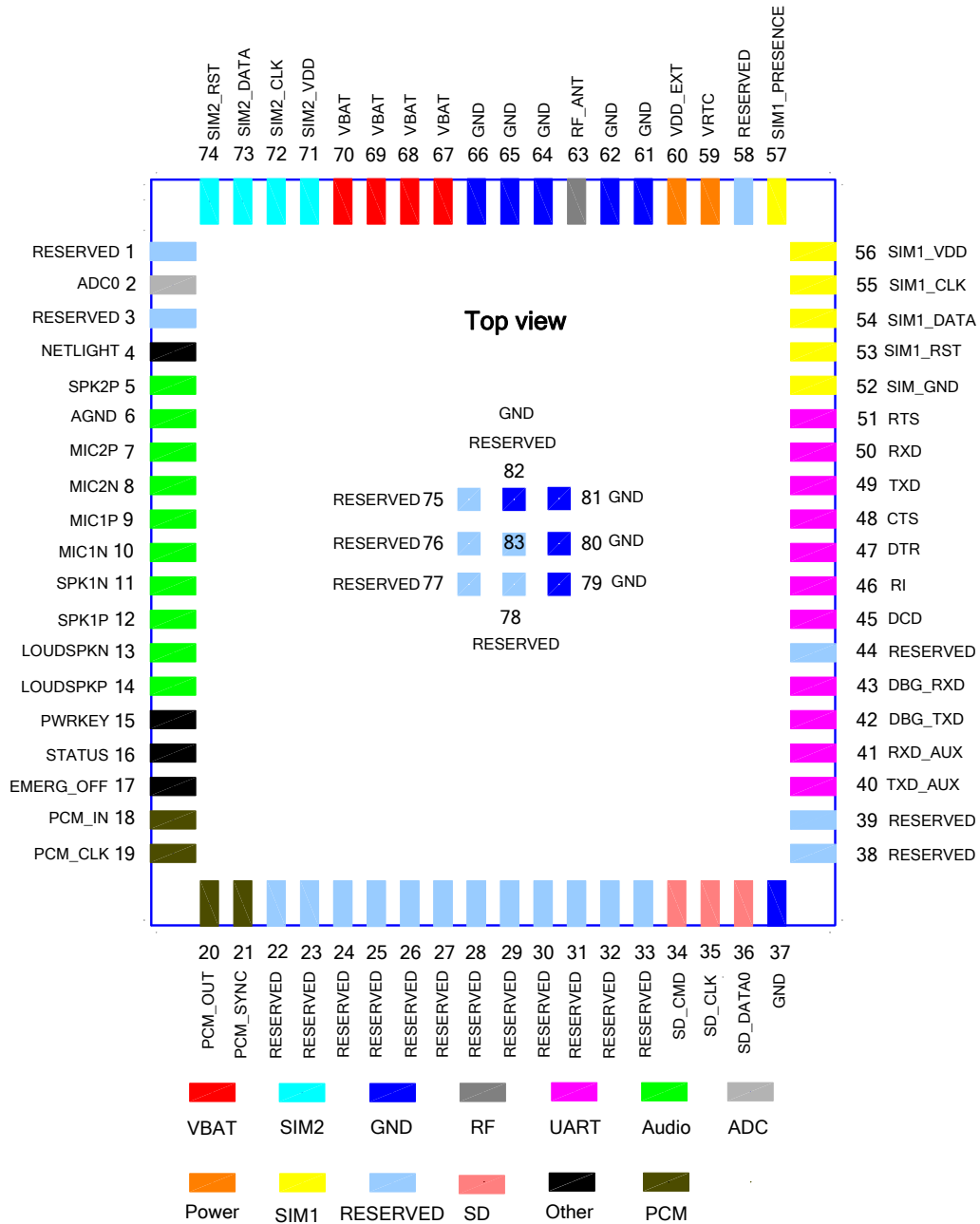


Figure 2: Pin Assignment

NOTE

Keep all reserved pins open.

3.1.2. Pin Description

Table 3: Pin Description

Power Supply					
PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
VBAT	67, 68, 69, 70	I	Main power supply of module: VBAT=3.3V~4.6V	Vmax=4.6V Vmin=3.3V Vnorm=4.0V	Make sure that supply sufficient current in a transmitting burst typically rises to 1.6A.
VRTC	59	I/O	Power supply for RTC. Charging for backup battery or golden capacitor when the VBAT is applied.	VImax=3.3V Vlmin=1.5V VInorm=2.8V VOMax=3V VOMin=2V VOnorm=2.8V Iout(max)=2mA Iin≈10uA	If unused, keep this pin open.
VDD_EXT	60	O	Supply 2.8V voltage for external circuit.	Vmax=2.9V Vmin=2.7V Vnorm=2.8V Imax=20mA	1. If unused, keep this pin open. 2. Recommend to add a 2.2~4.7uF bypass capacitor, when using this pin for power supply.
GND	37, 61, 62, 64~66, 79~82,		Ground		
Turn on/off					
PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
PWRKEY	15	I	Power on/off key. PWRKEY should be pulled down for a moment to turn on or turn off the system.	VILmax=0.1×VBAT VIHmin=0.6×VBAT VIHmax=3.1V	
Emergency Shutdown					

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
EMERG_ OFF	17	I	Emergency off. Pulled down for at least 40ms, which will turn off the module in case of emergency. Use it only when shutdown via PWRKEY or AT command cannot be achieved.	VILmax=0.45V VIHmin=1.35V Vopenmax=1.8V	Open drain/collector driver required in cellular device application. If unused, keep this pin open.

Module Indicator

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
STATUS	16	O	Indicate module's operating status. Output high level when module turns on, while output low level when module turns off.	VOHmin= 0.85×VDD_EXT VOLmax= 0.15×VDD_EXT	If unused, keep this pin open.

Audio Interface

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
MIC1P MIC1N	9, 10	I	Channel 1 positive and negative voice input	Refer to Section 3.8	If unused, keep these pins open.
MIC2P MIC2N	7, 8	I	Channel 2 positive and negative voice input		
SPK1P SPK1N	12, 11	O	Channel 1 positive and negative voice output		1. If unused, keep these pins open. 2. Support both voice and ringtone output.
SPK2P	5	O	Channel 2 voice output		
AGND	6		Analog ground. Separate ground connection for external audio circuits.		
LOUDSPKN LOUDSPKP	13, 14	O	Channel 3 positive and negative voice output		1. If unused, keep these pins open. 2. Integrate a Class- AB amplifier internally. 3. Support both voice and

ringtone output.

Network Status Indicator

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
NETLIGHT	4	O	Network status indication	VOHmin= 0.85×VDD_EXT VOLmax= 0.15×VDD_EXT	If unused, keep this pin open.

UART Port

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
DTR	47	I	Data terminal ready	VILmin=0V	
RXD	50	I	Receive data	VILmax= 0.25×VDD_EXT	If only use TXD, RXD and GND to communicate, recommended connecting RTS to GND via 0R resistor and keeping other pins open.
TXD	49	O	Transmit data	VIHmin= 0.75×VDD_EXT	
RTS	51	I	Request to send	VIHmax= VDD_EXT+0.2	
CTS	48	O	Clear to send	VOHmin= 0.85×VDD_EXT	
RI	46	O	Ring indication	VOLmax= 0.15×VDD_EXT	
DCD	45	O	Data carrier detection		

Debug Port

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
DBG_TXD	42	O	Transmit data	Same as above	If unused, keep these pins open.
DBG_RXD	43	I	Receive data		

Auxiliary Port

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
TXD_AUX	40	O	Transmit data	Same as above	If unused, keep these pins open.
RXD_AUX	41	I	Receive data		

SIM Interface

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
----------	---------	-----	-------------	--------------------	---------

SIM1_VDD	56	O	Power supply for SIM card	The voltage can be selected by software automatically. Either 1.8V or 3V.	
SIM2_VDD	71				
SIM1_CLK	55	O	SIM clock	VOLmax= 0.15×SIM_VDD VOHmin= 0.85×SIM_VDD	All signals of SIM interface should be protected against ESD with a TVS diode array. Maximum trace length is 200mm from the module pad to SIM card holder.
SIM2_CLK	72				
SIM1_DATA	54	I/O	SIM data	VILmax= 0.25×SIM_VDD VIHmin= 0.75×SIM_VDD VOLmax= 0.15×SIM_VDD VOHmin= 0.85×SIM_VDD	
SIM2_DATA	73				
SIM1_RST	53	O	SIM reset	VOLmax= 0.15×SIM_VDD VOHmin= 0.85×SIM_VDD	
SIM2_RST	74				
SIM1_PRESENCE	57	I	SIM card detection	VILmin=0V VILmax= 0.25×VDD_EXT VIHmin= 0.75×VDD_EXT VIHmax= VDD_EXT+0.2	If unused, keep these pins open.
SIM_GND	52		SIM ground		

ADC

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
ADC0	2	I	General purpose analog to digital converter.	Voltage range: 0V to 2.8V	If unused, keep this pin open.

PCM

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
PCM_CLK	19	O	PCM clock	VILmin= 0V	If unused, keep these pins open.
PCM_IN	18	I	PCM data input	VILmax= 0.25×VDD_EXT	

PCM_OUT	20	O	PCM data output	VIHmin= 0.75×VDD_EXT	
PCM_SYNC	21	O	PCM frame synchronization	VIHmax= VDD_EXT+0.2 VOHmin= 0.85×VDD_EXT VOLmax= 0.15×VDD_EXT	If unused, keep these pins open.

SD Card

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
SD_CMD	34	O	SD command	VILmin=0V VILmax= 0.25×VDD_EXT	
SD_CLK	35	O	SD clock	VIHmin= 0.75×VDD_EXT VIHmax= VDD_EXT+0.2	If unused, keep these pins open.
SD_DATA0	36	I/O	SD data	VOHmin= 0.85×VDD_EXT VOLmax= 0.15×VDD_EXT	

Antenna Interface

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
RF_ANT	63	I/O	RF antenna pad	Impedance of 50Ω	

Other Interface

PIN NAME	PIN NO.	I/O	DESCRIPTION	DC CHARACTERISTICS	COMMENT
RESERVD	1, 3, 22~33, 38, 39, 44, 58, 75~78, 83				Keep these pins open.

3.2. Operating Modes

The table below briefly summarizes the various operating modes in the following chapters.

Table 4: Overview of Operating Modes

Mode	Function	
Normal Operation	GSM/GPRS Sleep	After enabling sleep mode by AT+QSCLK=1 , the module will automatically go into Sleep Mode if DTR is set to high level and there is no interrupt (such as GPIO interrupt or data on UART port). In this case, the current consumption of module will reduce to the minimal level. During Sleep Mode, the module can still receive paging message and SMS from the system normally.
	GSM IDLE	Software is active. The module has registered to the GSM network, and the module is ready to send and receive GSM data.
	GSM TALK	GSM connection is ongoing. In this mode, the power consumption is decided by the configuration of Power Control Level (PCL), dynamic DTX control and the working RF band.
	GPRS IDLE	The module is not registered to GPRS network. The module is not reachable through GPRS channel.
	GPRS STANDBY	The module is registered to GPRS network, but no GPRS PDP context is active. The SGSN knows the Routing Area where the module is located at.
	GPRS READY	The PDP context is active, but no data transfer is ongoing. The module is ready to receive or send GPRS data. The SGSN knows the cell where the module is located at.
	GPRS DATA	There is GPRS data in transfer. In this mode, power consumption is decided by the PCL, working RF band and GPRS multi-slot configuration.
POWER DOWN	Normal shutdown by sending the AT+QPOWD=1 command or using the PWRKEY or the EMERG_OFF ¹⁾ pin. The power management ASIC disconnects the power supply from the base band part of the module, and only the power supply for the RTC is remained. Software is not active. The UART interfaces are not accessible. Operating voltage (connected to VBAT) remains applied.	
Minimum Functionality Mode (without removing power supply)	AT+CFUN command can set the module to a minimum functionality mode without removing the power supply. In this case, the RF part of the module will not work or the SIM card will not be accessible, or both RF part and SIM card will be disabled, but the UART port is still accessible. The power consumption in this case is very low.	

NOTE

Use the EMERG_OFF pin only when failing to turn off the module by the command **AT+QPOWD=1** and the PWRKEY pin. For more details, please refer to the **Section 3.4.2.4**.

3.3. Power Supply

3.3.1. Power Features of Module

The power supply is one of the key issues in designing GSM terminals. Because of the 577us radio burst in GSM every 4.615ms, power supply must be able to deliver high current peaks in a burst period. During these peaks, drops on the supply voltage must not exceed minimum working voltage of module.

For the M85 module, the max current consumption could reach to 1.6A during a transmit burst. It will cause a large voltage drop on the VBAT. In order to ensure stable operation of the module, it is recommended that the max voltage drop during the transmit burst does not exceed 400mV.

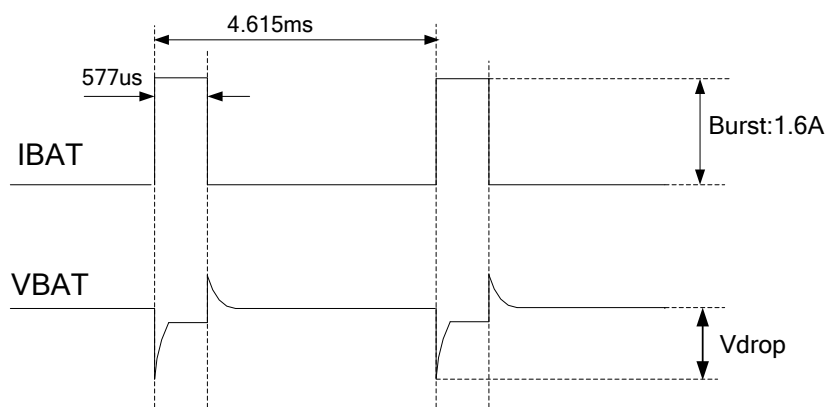


Figure 3: Voltage Ripple during Transmitting

3.3.2. Decrease Supply Voltage Drop

The power supply range of the module is 3.3V to 4.6V. Make sure that the input voltage will never drop below 3.3V even in a transmitting burst. If the power voltage drops below 3.3V, the module could turn off automatically. For better power performance, it is recommended to place a 100uF tantalum capacitor with low ESR (ESR=0.7Ω) and ceramic capacitor 100nF, 33pF and 10pF near the VBAT pin. The reference circuit is illustrated in Figure 4.

The VBAT route should be wide enough to ensure that there is not too much voltage drop during transmit burst. The width of trace should be no less than 2mm and the principle of the VBAT route is the longer route, the wider trace.

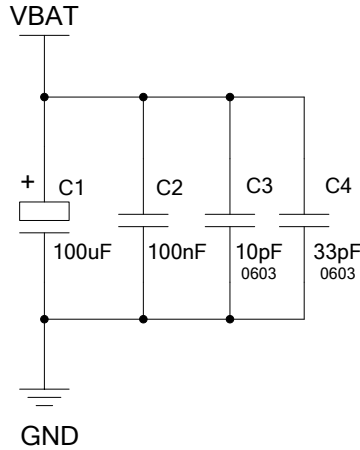


Figure 4: Reference Circuit for the VBAT Input

3.3.3. Reference Design For Power Supply

The power design for the module is very important, since the performance of power supply for the module largely depends on the power source. The power supply is capable of providing the sufficient current up to 2A at least. If the voltage drop between the input and output is not too high, it is suggested to use a LDO as module's power supply. If there is a big voltage difference between the input source and the desired output (VBAT), a switcher power converter is recommended to use as a power supply.

Figure 5 shows a reference design for +5V input power source. The designed output for the power supply is 4.0V and the maximum load current is 3A. In addition, in order to get a stable output voltage, a zener diode is placed close to the pins of VBAT. As to the zener diode, it is suggested to use a zener diode whose reverse zener voltage is 5.1V and dissipation power is more than 1 Watt.

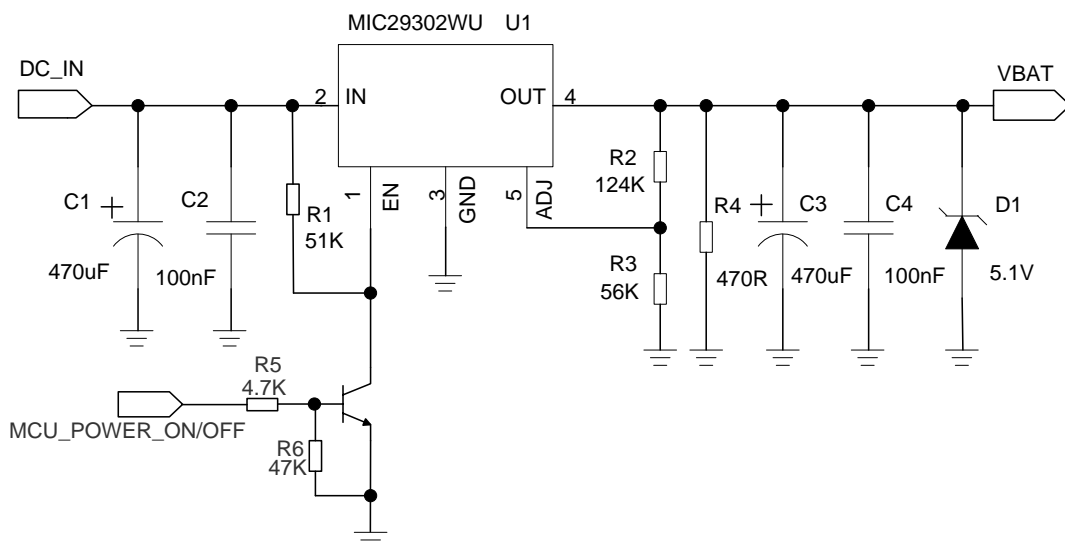


Figure 5: Reference Circuit for Power Supply

NOTE

It is suggested to control the module's main power supply (VBAT) via LDO enable pin to restart the module when the module has become abnormal. Power switch circuit like P-channel MOSFET switch circuit can also be used to control VBAT.

3.3.4. Monitor Power Supply

The command **AT+CBC** can be used to monitor the supply voltage of the module. The unit of the displayed voltage is mV.

For details, please refer to the **document [1]**.

3.4. Power On and Down Scenarios

3.4.1. Power On

The module can be turned on by driving the pin PWRKEY to a low level voltage. An open collector driver circuit is suggested to control the PWRKEY. A simple reference circuit is illustrated as below.

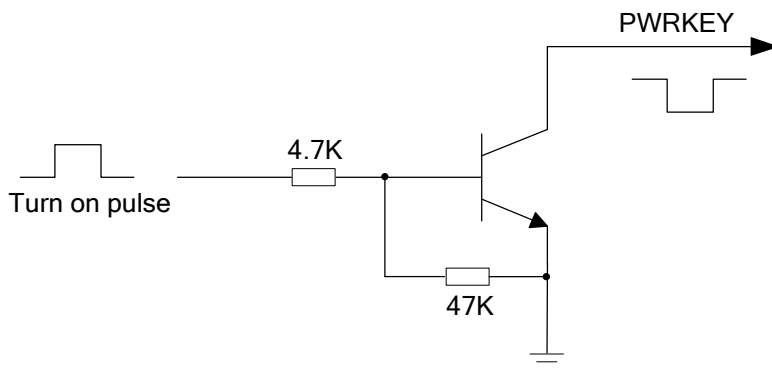


Figure 6: Turn on the Module with an Open-collector Driver

NOTES

1. M85 module is set to autobauding mode (**AT+IPR=0**) by default. In the autobauding mode, URC "RDY" is not reported to the host controller after module is powered on. When the module is powered on after a delay of 4 or 5 seconds, it can receive AT command. Host controller should first send an **AT** string in order that the module can detect baud rate of host controller, and it should continue to send the next **AT** string until receiving **OK** string from the module. Then enter **AT+IPR=x;&W** to set a fixed baud rate for the module and save the configuration to flash memory of the module. After these

configurations, the URC **RDY** would be received from the UART Port of the module every time when the module is powered on. For more details, refer to the section **AT+IPR** in **document [1]**.

2. AT command response indicates module is turned on successfully, or else the module fails to be turned on.

The other way to control the PWRKEY is through a button directly. A TVS component is indispensable to be placed nearby the button for ESD protection. For the best performance, the TVS component must be placed nearby the button. When pressing the key, electrostatic strike may generate from finger. A reference circuit is shown in the following figure.

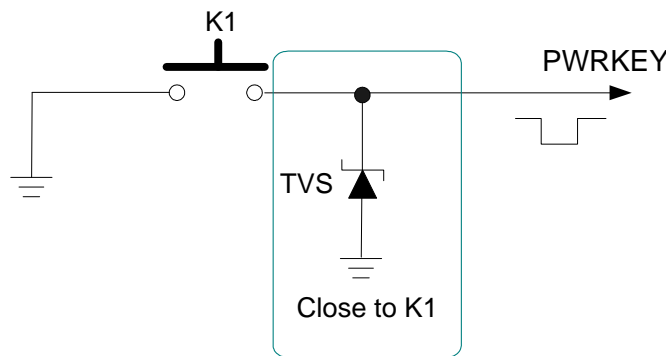


Figure 7: Turn on the Module with a Button

The turn-on timing is illustrated as the following figure.

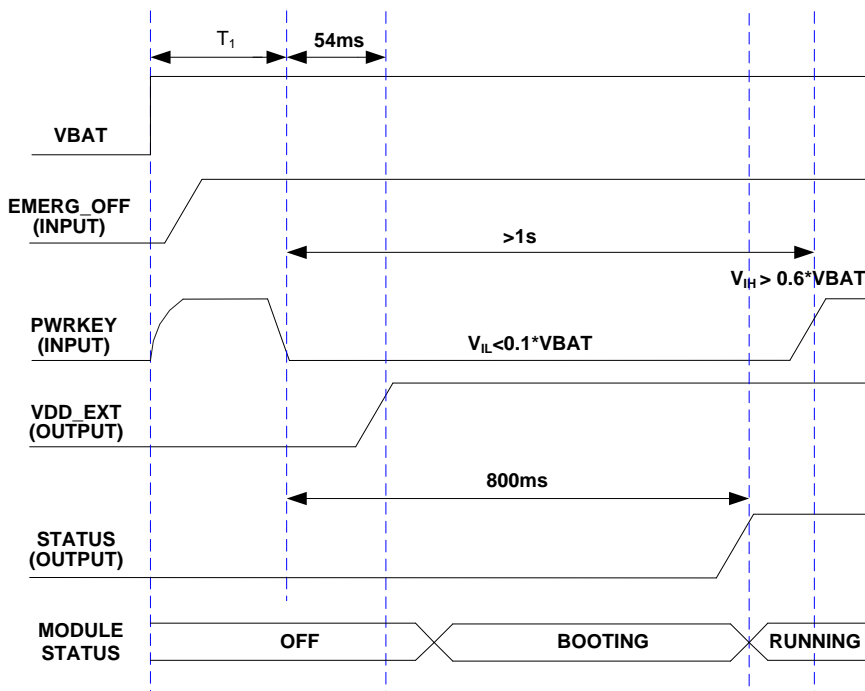


Figure 8: Turn-on Timing

NOTES

1. Make sure that VBAT is stable before pulling down PWRKEY pin. The time of T_1 is recommended as 100ms.
2. EMERG_OFF should be floated when it is unused.
3. For more details about the application of STATUS pin, please refer to the **Chapter 3.15**.

3.4.2. Power Down

The following procedures can be used to turn off the module:

- Normal power down procedure: Turn off module using the PWRKEY pin.
- Normal power down procedure: Turn off module using command **AT+QPOWD**.
- Over-voltage or under-voltage automatic shutdown: Take effect when over-voltage or under-voltage is detected.
- Emergent power down procedure: Turn off module using the EMERG_OFF pin.

3.4.2.1. Power Down Module Using the PWRKEY Pin

It is a safe way to turn off the module by driving the PWRKEY to a low level voltage for a certain time. The power down scenario is illustrated as the following figure.

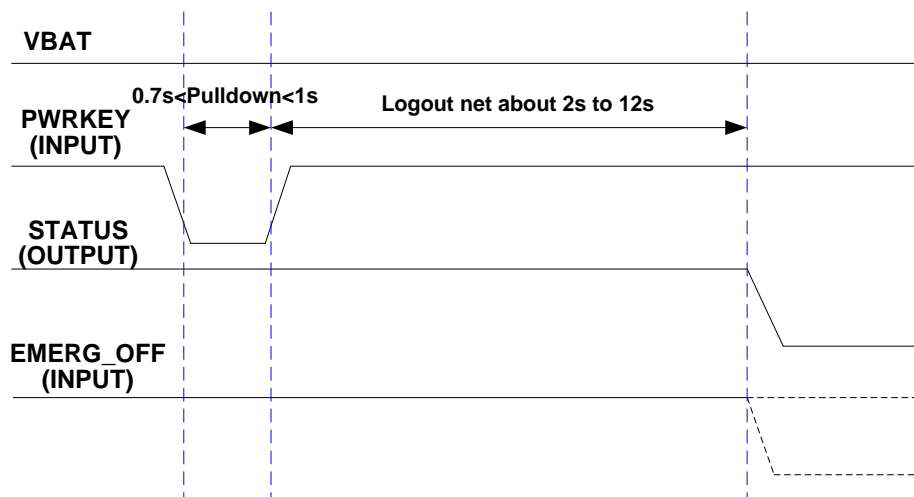


Figure 9: Turn-off timing

The power down procedure causes the module to log off from the network and allows the firmware to save important data before completely disconnecting the power supply.

Before the completion of the power down procedure, module sends out the result code shown as below:

NORMAL POWER DOWN

After that moment, no further AT commands can be executed. Then the module enters the power down mode, only the RTC is still active. The power down mode can also be indicated by the STATUS pin, which is a low level voltage in this mode.

NOTES

1. This unsolicited result codes do not appear when autobauding is active and DTE and DCE are not correctly synchronized after start-up. The module is recommended to set to a fixed baud rate.
2. As logout network time is related to the local mobile network, it is recommended to delay about 12 seconds before disconnecting the power supply or restarting the module.
3. For more details about the application of STATUS pin, please refer to the **Chapter 3.15**.

3.4.2.2. Power Down Module Using AT Command

It is also a safe way to turn off the module via AT command **AT+QPOWD=1**. This command will let the module to log off from the network and allow the firmware to save important data before completely disconnecting the power supply.

Before the completion of the power down procedure, module sends out the result code shown as below:

NORMAL POWER DOWN

After that moment, no further AT commands can be executed. And then the module enters the power down mode, only the RTC is still active.

Please refer to the **document [1]** for details about the AT command **AT+QPOWD**.

3.4.2.3. Over-voltage or Under-voltage Automatic Shutdown

The module will constantly monitor the voltage applied on the VBAT, if the voltage is $\leq 3.5V$, the following URC will be presented:

UNDER_VOLTAGE WARNING

If the voltage is $\geq 4.5V$, the following URC will be presented:

OVER_VOLTAGE WARNING

The normal input voltage range is from 3.3V to 4.6V. If the voltage is >4.6V or <3.3V, the module would automatically shut down itself.

If the voltage is <3.3V, the following URC will be presented:

UNDER_VOLTAGE POWER DOWN

If the voltage is >4.6V, the following URC will be presented:

OVER_VOLTAGE POWER DOWN

After that moment, no further AT commands can be executed. The module logs off from network and enters power down mode, and only RTC is still active.

NOTES

1. These unsolicited result codes do not appear when autobauding is active and DTE and DCE are not correctly synchronized after start-up. The module is recommended to set to a fixed baud rate.
2. Over-voltage warning and shutdown function is disabled by default.

3.4.2.4. Emergency Shutdown Using EMERG_OFF Pin

The module can be shut down by driving the pin EMERG_OFF to a low level voltage over 40ms and then releasing it. The EMERG_OFF line can be driven by an open-drain/collector driver or a button. The circuit is illustrated as the following figures.

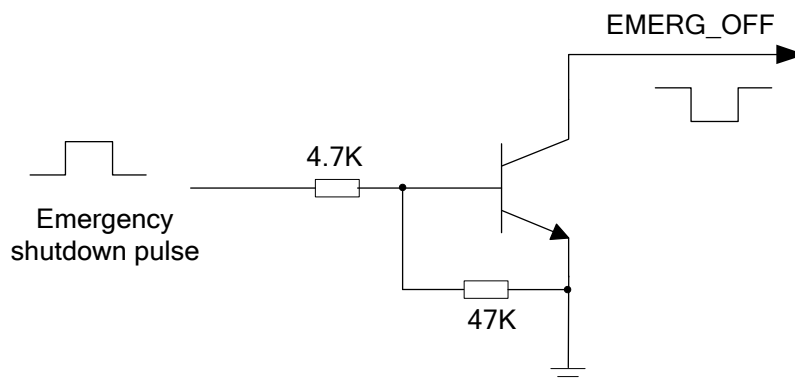


Figure 10: An Open-collector Driver for EMERG_OFF

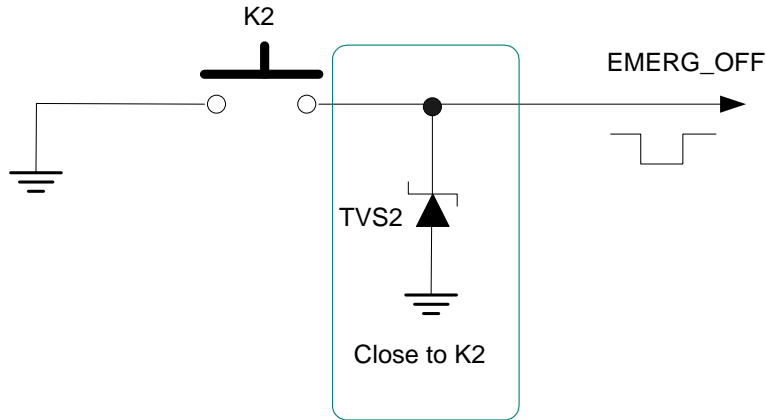


Figure 11: Reference Circuit for EMERG_OFF by Using Button

Be cautious to use the pin EMERG_OFF. It should only be used under emergent situation. For instance, if the module is unresponsive or abnormal, the pin EMERG_OFF could be used to shut down the system. Although turning off the module by EMERG_OFF is fully tested and nothing wrong detected, this operation is still a big risk as it could cause destroying of the code or data area of the flash memory in the module. Therefore, it is recommended that PWRKEY or AT command should always be the preferential way to turn off the system.

3.4.3. Restart

The module can be restarted by driving the PWRKEY to a low level voltage for a certain time, which is similar to the way of turning on module. In order to make the internal LDOs discharge completely after turning off the module, it is recommended to delay about 500ms before restarting the module. The restart timing is illustrated as the following figure.

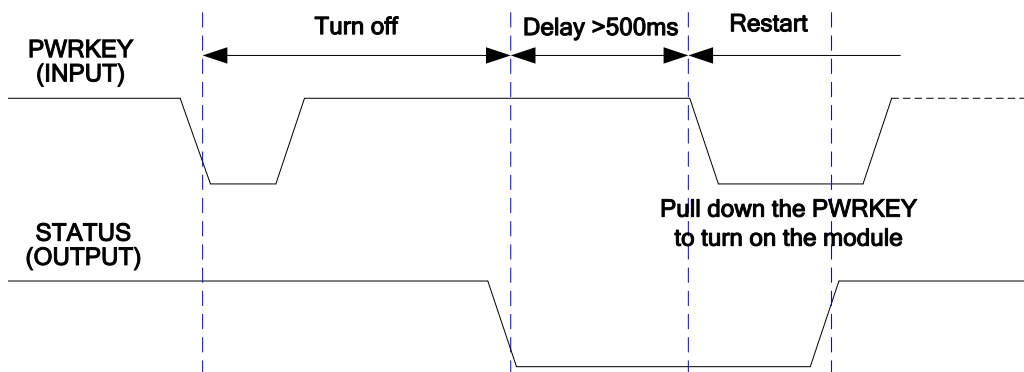


Figure 12: Timing of Restarting System

The module can also be restarted by the PWRKEY after emergency shutdown.

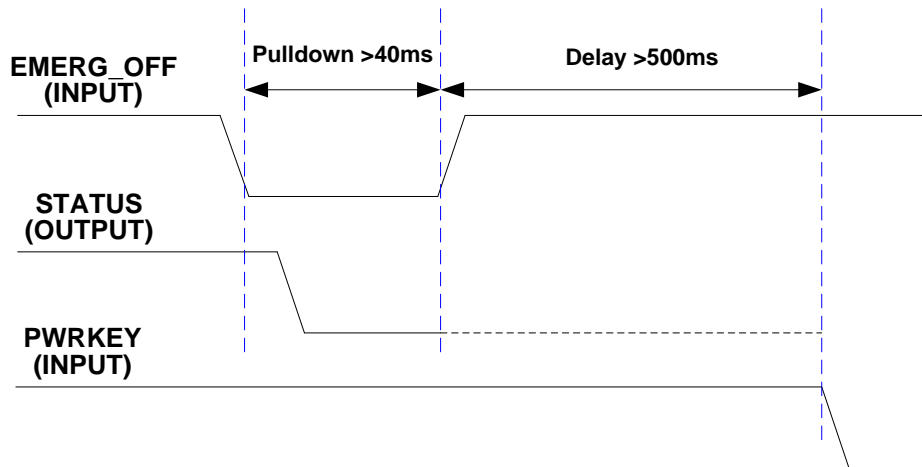


Figure 13: Timing of Restarting System after Emergency Shutdown

NOTE

For more details about the application of STATUS pin, please refer to the **Chapter 3.15**.

3.5. Power Saving

Based on system requirements, there are several actions to drive the module to enter low current consumption status. For example, **AT+CFUN** can be used to set module into minimum functionality mode and DTR hardware interface signal can be used to lead system to SLEEP mode.

3.5.1. Minimum Functionality Mode

Minimum functionality mode reduces the functionality of the module to a minimum level. The consumption of the current can be minimized when the slow clocking mode is activated at the same time. The mode is set with the **AT+CFUN** command which provides the choice of the functionality levels $\langle \text{fun} \rangle = 0, 1, 4$.

- 0: minimum functionality
- 1: full functionality (default)
- 4: disable both transmitting and receiving of RF part

If the module is set to minimum functionality by **AT+CFUN=0**, the RF function and SIM card function would be disabled. In this case, the UART port is still accessible, but all AT commands related with RF function or SIM card function will be not available.

If the module has been set by the command with **AT+CFUN=4**, the RF function will be disabled, but the UART port is still active. In this case, all AT commands related with RF function will be not available.

After the module is set by **AT+CFUN=0** or **AT+CFUN=4**, it can return to full functionality by **AT+CFUN=1**.

For detailed information about **AT+CFUN**, please refer to the *document [1]*.

3.5.2. SLEEP Mode

The SLEEP mode is disabled by default. You can enable it by **AT+QSCLK=1**. On the other hand, the default setting is **AT+QSCLK=0** and in this mode, the module cannot enter SLEEP mode.

When the module is set by the command with **AT+QSCLK=1**, you can control the module to enter or exit from the SLEEP mode through pin DTR. When DTR is set to high level, and there is no on-air or hardware interrupt such as GPIO interrupt or data on UART port, the module will enter SLEEP mode automatically. In this mode, the module can still receive voice, SMS or GPRS paging from network, but the UART port does not work.

3.5.3. Wake up Module from SLEEP Mode

When the module is in the SLEEP mode, the following methods can wake up the module.

- If the DTR Pin is set low, it would wake up the module from the SLEEP mode. The UART port will be active within 20ms after DTR is changed to low level.
- Receive a voice or GPRS data from network wakes up module.
- Receive an SMS from network wakes up module.

NOTE

DTR pin should be held at low level during communication between the module and DTE.

3.5.4. Summary of State Transition

Table 5: Summary of State Transition

Current Mode	Next Mode		
	Power Down	Normal Mode	Sleep Mode
Power Down		Use PWRKEY	

Normal Mode	AT+QPOWD , use PWRKEY pin, or use EMERG_OFF pin	Use AT command AT+QSCLK=1 and pull up DTR
SLEEP Mode	Use PWRKEY pin, or use EMERG_OFF pin	Pull DTR down or incoming voice call or SMS or GPRS data transmission

3.6. RTC Backup

The RTC (Real Time Clock) function is supported. The RTC is designed to work with an internal power supply.

There are three kinds of designs for RTC backup power:

- Use VBAT as the RTC power source

When the module is turned off and the main power supply (VBAT) is remained, the real time clock is still active as the RTC core is supplied by VBAT. In this case, the VRTC pin can be kept floating.

- Use VRTC as the RTC power source

If the main power supply (VBAT) is removed after the module is turned off, a backup supply such as a coin-cell battery (rechargeable or non-chargeable) or a super-cap can be used to supply the VRTC pin to keep the real time clock active.

- Use VBAT and VRTC as the RTC power source

As only power the VRTC pin to keep the RTC will lead an error about 5 minutes a day, it is recommended to power VBAT and VRTC pin at the same time when RTC function is needed. The recommended supply for RTC core circuits are shown as below.

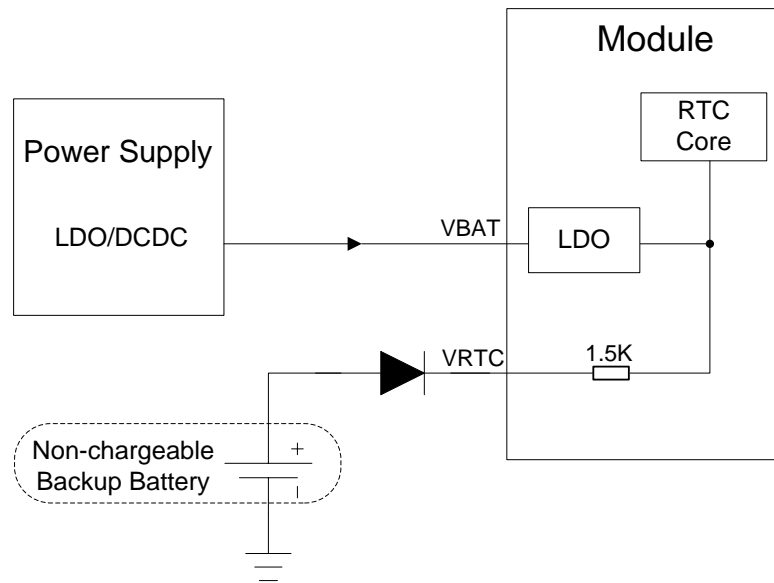


Figure 14: VRTC is Supplied by a Non-chargeable Battery

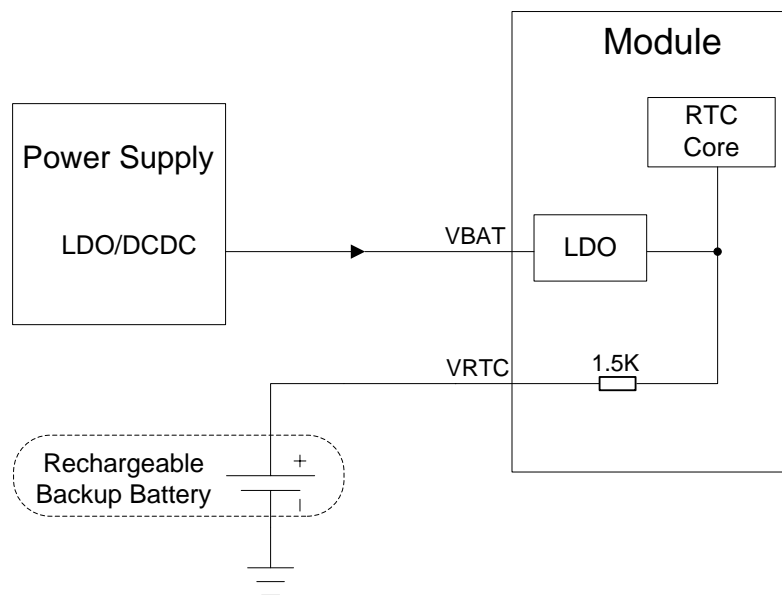


Figure 15: VRTC is Supplied by a Rechargeable Battery

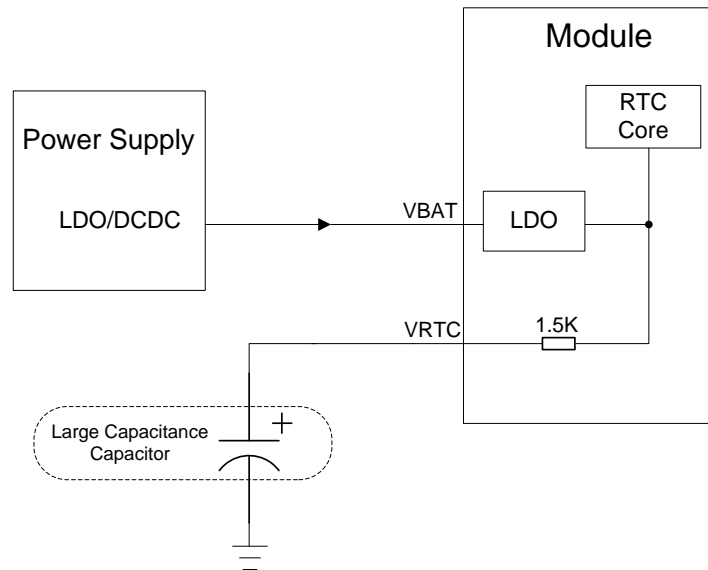


Figure 16: VRTC is Supplied by a Capacitor

For the choice of a rechargeable or non-chargeable coin-cell battery, please visit <http://www.sii.co.jp/en/>.

NOTE

If you want to keep an accurate real time, please keep the main power supply VBAT alive.

3.7. Serial Interfaces

The module provides three serial ports: UART Port, Debug Port and Auxiliary Port. The module is designed as a DCE (Data Communication Equipment), following the traditional DCE-DTE (Data Terminal Equipment) connection. Autobauding function supports baud rate from 4800bps to 115200bps.

The UART Port:

- TXD: Send data to RXD of DTE.
- RXD: Receive data from TXD of DTE.
- RTS: Request to send.
- CTS: Clear to send.
- DTR: DTE is ready and inform DCE (this pin can wake the module up).
- RI: Ring indicator (when there is a call, SMS or URC output, the module will inform DTE with the RI pin).
- DCD: Data carrier detection (the validity of this pin demonstrates the communication link is set up).

NOTE

Hardware flow control is disabled by default. When hardware flow control is required, RTS and CTS should be connected to the host. AT command **AT+IFC=2,2** is used to enable hardware flow control. AT command **AT+IFC=0,0** is used to disable the hardware flow control. For more details, please refer to the **document [1]**.

The Debug Port:

- DBG_TXD: Send data to the COM port of computer.
- DBG_RXD: Receive data from the COM port of computer.

The Auxiliary UART Port:

- TXD_AUX: Send data to the RXD of DTE.
- RXD_AUX: Receive data from the TXD of DTE.

The logic levels are described in the following table.

Table 6: Logic Levels of the UART Interface

Parameter	Min.	Max.	Unit
V _{IL}	0	0.25×VDD_EXT	V
V _{IH}	0.75×VDD_EXT	VDD_EXT +0.2	V
V _{OL}	0	0.15×VDD_EXT	V
V _{OH}	0.85×VDD_EXT	VDD_EXT	V

Table 7: Pin Definition of the UART Interfaces

Interface	Pin Name	Pin No.	Description
Debug Port	DBG_RXD	43	Receive data
	DBG_TXD	42	Transmit data
UART Port	DCD	45	Data carrier detection
	RI	46	Ring indication

	DTR	47	Data terminal ready
	CTS	48	Clear to send
	TXD	49	Transmit data
	RXD	50	Receive data
	RTS	51	Request to send
Auxiliary UART Port	TXD_AUX	40	Transmit data
	RXD_AUX	41	Receive data

3.7.1. UART Port

3.7.1.1. The Features of UART Port

- Contain data lines TXD and RXD, hardware flow control lines RTS and CTS, other control lines DTR, DCD and RI.
- Used for AT command, GPRS data, etc. Multiplexing function is supported on the UART Port. So far only the basic mode of multiplexing is available.
- Support the communication baud rates as the following:
300, 600, 1200, 2400, 4800, 9600, 14400, 19200, 28800, 38400, 57600 and 115200.
- The default setting is autobauding mode. Support the following baud rates for autobauding function:
4800, 9600, 19200, 38400, 57600 and 115200.
- The module disables hardware flow control by default. AT command **AT+IFC=2,2** is used to enable hardware flow control.

After setting a fixed baud rate or autobauding, please send **AT** string at that rate. The UART port is ready when it responds **OK**.

Autobauding allows the module to detect the baud rate by receiving the string **AT** from the host or PC automatically, which gives module flexibility without considering which baud rate is used by the host controller. Autobauding is enabled by default. To take advantage of the autobauding mode, special attention should be paid according to the following requirements:

1. Synchronization between DTE and DCE

When DCE (the module) powers on with the autobauding enabled, it is recommended to wait 4 or 5 seconds before sending the first AT character. After receiving the **OK** response, DTE and DCE are correctly synchronized.

If the host controller needs URC in the mode of autobauding, it must be synchronized firstly. Otherwise the URC will be discarded.

2. Restrictions on autobauding operation

- The UART port has to be operated at 8 data bits, no parity and 1 stop bit (factory setting).
- Only the strings “AT” or “at” can be detected (neither “At” nor “aT”).
- The Unsolicited Result Codes like “RDY”, “+CFUN: 1” and “+CPIN: READY” will not be indicated when the module is turned on with autobauding enabled and not be synchronized.
- Any other Unsolicited Result Codes will be sent at the previous baud rate before the module detects the new baud rate by receiving the first AT string. The DTE may receive unknown characters after switching to new baud rate.
- It is not recommended to switch to autobauding from a fixed baud rate.
- If autobauding is active it is not recommended to switch to multiplex mode.

NOTE

To assure reliable communication and avoid any problems caused by undetermined baud rate between DCE and DTE, it is strongly recommended to configure a fixed baud rate and save it instead of using autobauding after start-up. For more details, please refer to the Section **AT+IPR** in **document [1]**.

3.7.1.2. The Connection of UART Port

The connection between module and host using UART Port is very flexible. Three connection styles are illustrated as below.

Reference design for Full-Function UART connection is shown as below when it is applied in modulation-demodulation.

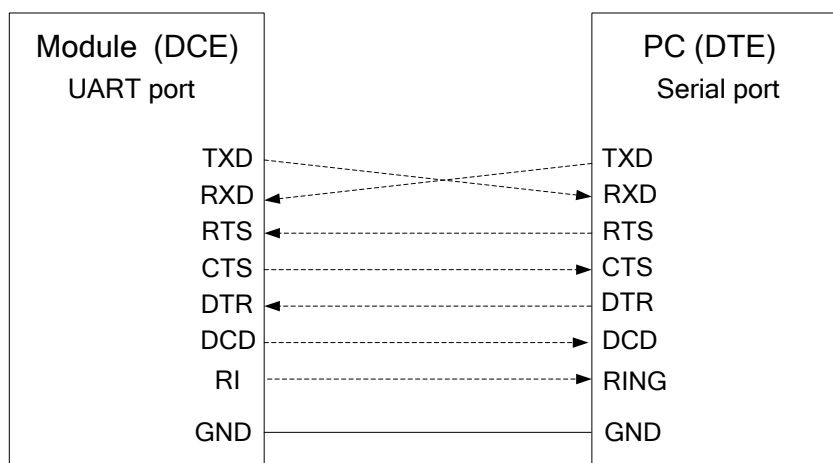


Figure 17: Reference Design for Full-Function UART

Three-line connection is shown as below.

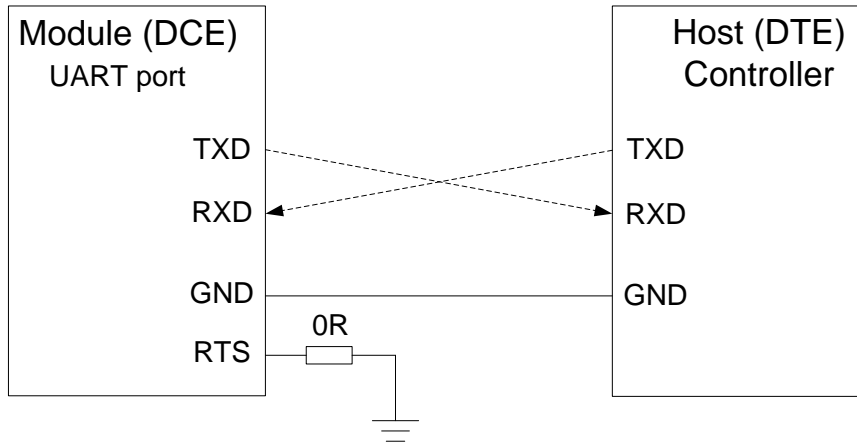


Figure 18: Reference Design for UART Port

UART Port with hardware flow control is shown as below. This connection will enhance the reliability of the mass data communication.

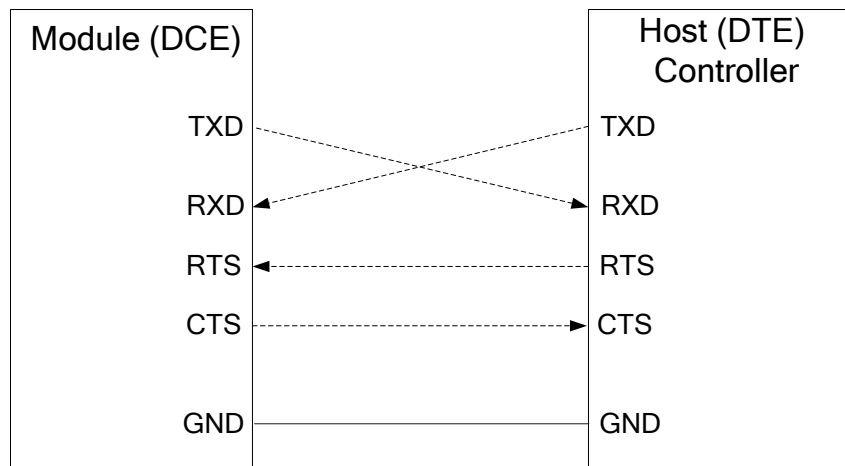


Figure 19: Reference Design for UART Port with Hardware Flow Control

3.7.1.3. Firmware Upgrade

The TXD, RXD can be used to upgrade firmware. The PWRKEY pin must be pulled down before firmware upgrade. The reference circuit is shown as below:

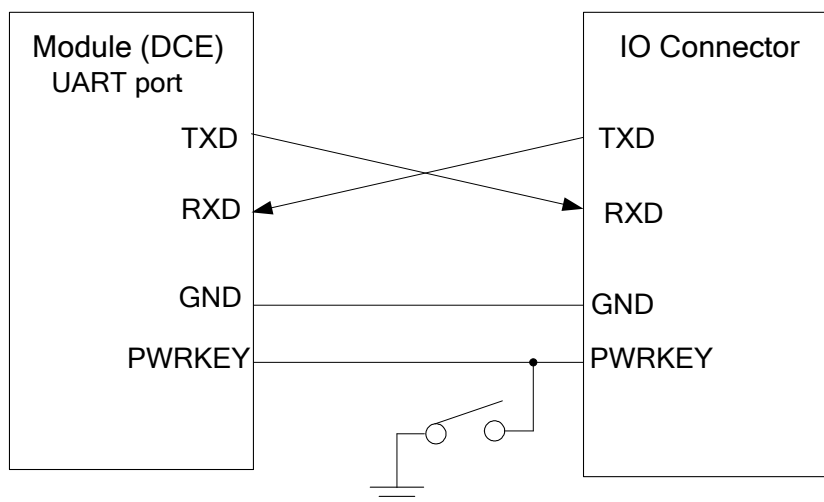


Figure 20: Reference Design for Firmware Upgrade

NOTE

The firmware of module might need to be upgraded due to certain reasons. It is recommended to reserve these pins in the host board for firmware upgrade.

3.7.2. Debug Port

- Two lines: DBG_TXD and DBG_RXD
- It outputs log information automatically.
- Debug Port is only used for firmware debugging and its baud rate must be configured as 460800bps.

The reference design for Debug Port is shown as below.

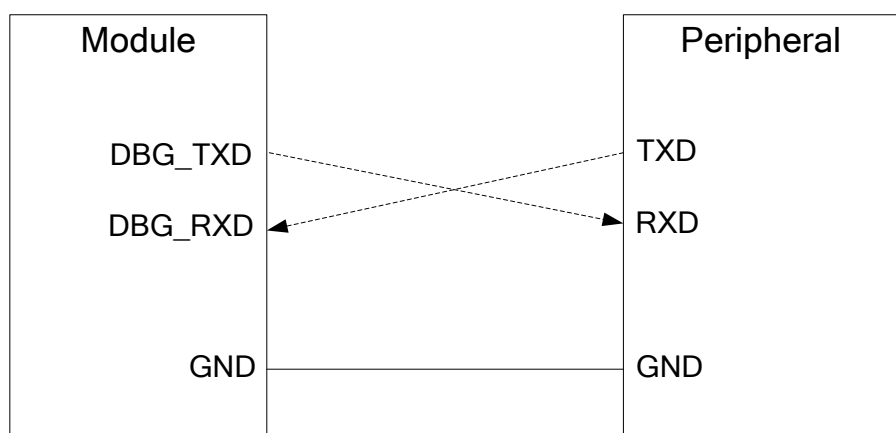


Figure 21: Reference Design for Debug Port

3.7.3. Auxiliary UART Port

- Two data lines: TXD_AUX and RXD_AUX.
- Auxiliary UART port is used for AT command only and does not support GPRS data, multiplexing function etc.
- Auxiliary UART port supports the communication baud rates as the following:
1200, 2400, 4800, 9600, 14400, 19200, 28800, 38400, 57600, 115200bps.
- Auxiliary UART port could be used when you send **AT+QEAUART=1** string on the UART port.
- The default baud rate setting is 115200bps, and does not support autobauding. The baud rate can be modified by **AT+QSEDCB** command. For more details, please refer to the **document [1]**.

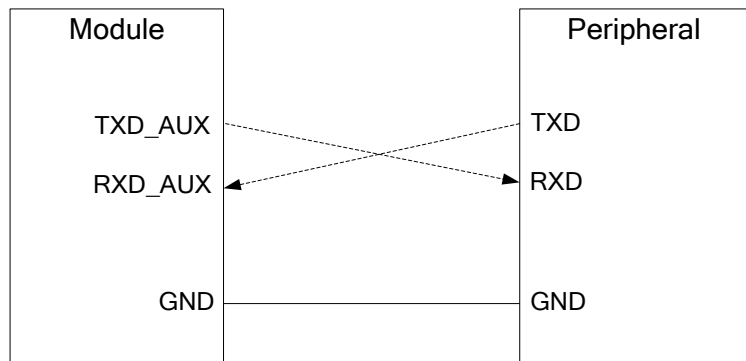


Figure 22: Reference Design for Auxiliary UART Port

3.7.4. UART Application

The reference design of 3.3V level match is shown as below. If the host is a 3V system, please change the 5.6K resistor to 10K.

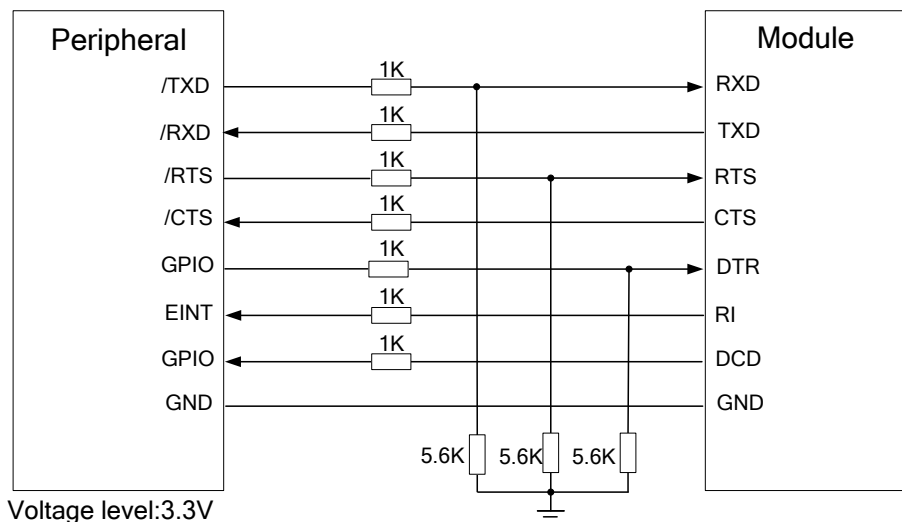


Figure 23: Level Match Design for 3.3V System

NOTE

It is highly recommended to add the resistor divider circuit on the UART signal lines when the host's level is 3V or 3.3V. For the higher voltage level system, a level shifter IC could be used between the host and the module. For more details about UART circuit design, please refer to **document [11]**.

The following figure shows a sketch map between module and standard RS-232 interface. Since the electrical level of module is 2.8V, so a RS-232 level shifter must be used. Note that you should assure the IO voltage of level shifter which connects to module is 2.8V.

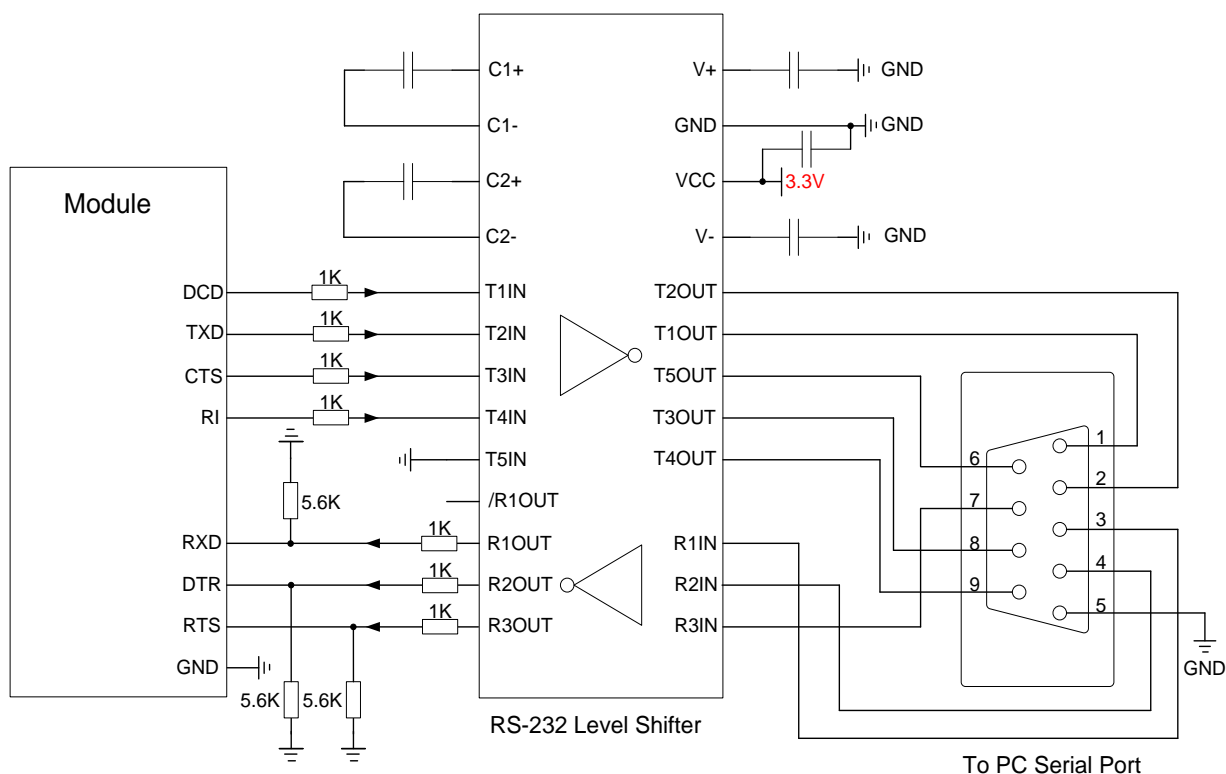


Figure 24: Sketch Map for RS-232 Interface Match

Please visit vendor website to select the suitable RS-232 level shifter IC, such as: <http://www.exar.com/> and <http://www.maximintegrated.com>.

3.8. Audio Interfaces

The module provides two analogy input channels and three analogy output channels.

Table 8: Pin Definition of Audio Interface

Interface	Pin Name	Pin No.	Description
AIN1/AOUT1	MIC1P	9	Channel 1 Microphone positive input
	MIC1N	10	Channel 1 Microphone negative input
	SPK1P	12	Channel 1 Audio positive output
	SPK1N	11	Channel 1 Audio negative output
AIN2/AOUT2	MIC2P	7	Channel 2 Microphone positive input
	MIC2N	8	Channel 2 Microphone negative input
	SPK2P	5	Channel 2 Audio positive output
	AGND	6	Form a pseudo-differential pair with SPK2P
AOUT3	LOUDSPKP	14	Channel 3 Audio positive output
	LOUDSPKN	13	Channel 3 Audio negative output

AIN1 and AIN2 can be used for input of microphone and line. An electret microphone is usually used. AIN1 and AIN2 are both differential input channels.

AOUT1 is used for output of the receiver. This channel is typically used for a receiver built into a handset. AOUT1 channel is a differential channel.

AOUT2 is typically used with earphone. It is a single-ended and mono channel. SPK2P and AGND can establish a pseudo differential mode.

AOUT2 can also be used for output of receiver, which can be used as a single-ended channel. SPK2P and AGND can establish a pseudo differential mode.

AOUT3 is used for loud speaker output as it embedded an amplifier of class AB whose maximum drive power is 870mW.

All of these three audio channels support voice and ringtone output, and so on, and can be switched by **AT+QAUDCH** command. For more details, please refer to the **document [1]**.

Use AT command **AT+QAUDCH** to select audio channel:

- 0--AIN1/AOUT1, the default value is 0.
- 1--AIN2/AOUT2
- 2--AIN2/AOUT3

For each channel, you can use **AT+QMIC** to adjust the input gain level of microphone. Customer can also use **AT+CLVL** to adjust the output gain level of receiver and speaker. **AT+QSIDET** is used to set the side-tone gain level. For more details, please refer to the *document [1]*.

Table 9: AOUT3 Output Characteristics

Item	Condition	Min.	Type	Max.	Unit
RMS Power	8ohm load VBAT=4.2V THD+N=1%		870		mW
	8ohm load VBAT=3.3V THD+N=1%		530		mW

3.8.1. Decrease TDD Noise and Other Noise

The 33pF capacitor is applied for filtering out 900MHz RF interference when the module is transmitting at EGSM900MHz. Without placing this capacitor, TDD noise could be heard. Moreover, the 10pF capacitor here is for filtering out 1800MHz RF interference. However, the resonant frequency point of a capacitor largely depends on the material and production technique. Therefore, you would have to discuss with its capacitor vendor to choose the most suitable capacitor for filtering out GSM850MHz, EGSM900MHz, DCS1800MHz and PCS1900MHz separately.

The severity degree of the RF interference in the voice channel during GSM transmitting period largely depends on the application design. In some cases, GSM900 TDD noise is more severe; while in other cases, DCS1800 TDD noise is more obvious. Therefore, you can have a choice based on test results. Sometimes, even no RF filtering capacitor is required.

The capacitor which is used for filtering out RF noise should be close to audio interface. Audio alignment should be as short as possible.

In order to decrease radio or other signal interference, the position of RF antenna should be kept away from audio interface and audio alignment. Power alignment and audio alignment should not be parallel, and power alignment should be far away from audio alignment.

The differential audio traces have to be placed according to the differential signal layout rule.

3.8.2. Microphone Interfaces Design

AIN1 and AIN2 channels come with internal bias supply for external electret microphone. A reference circuit is shown in the following figure.

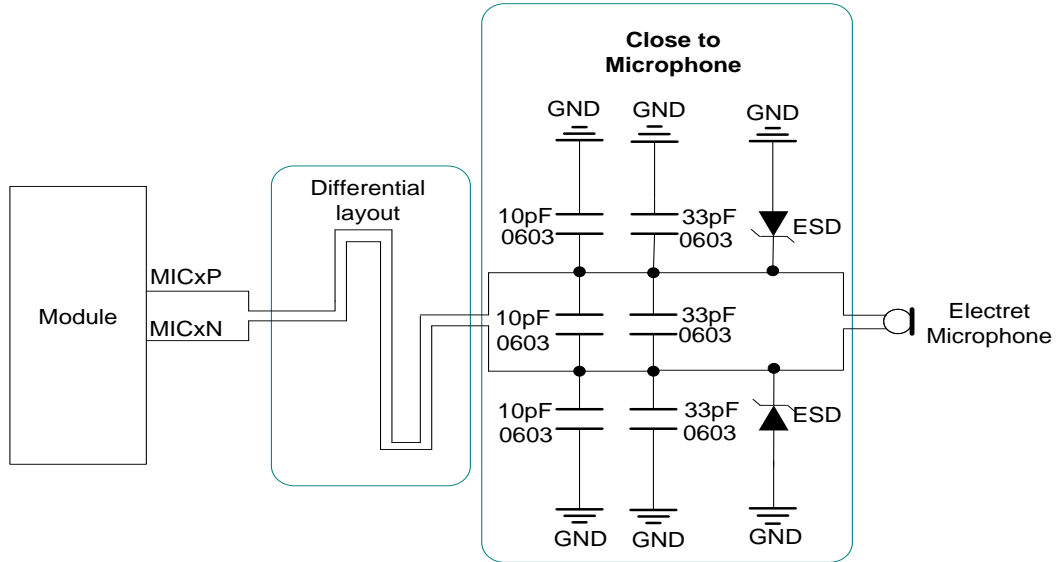


Figure 25: Reference Design for AIN1&AIN2

3.8.3. Receiver and Speaker Interface Design

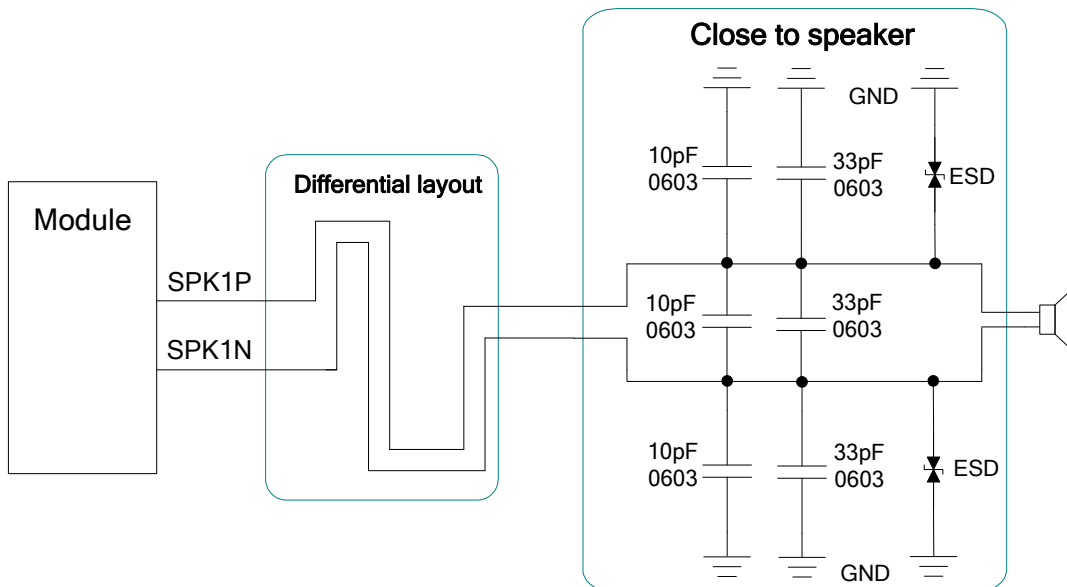


Figure 26: Handset Interface Design for AOUT1

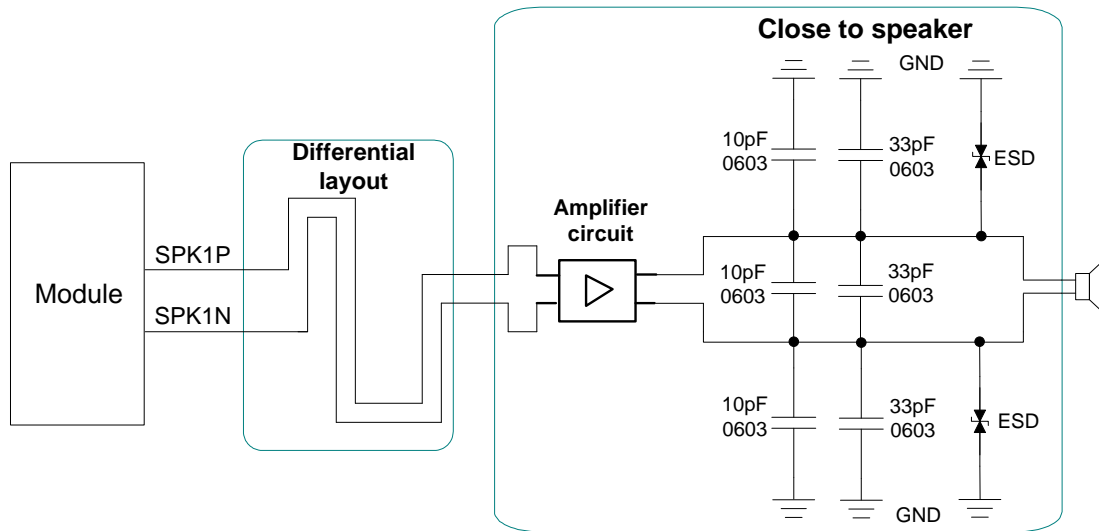


Figure 27: Speaker Interface Design with an Amplifier for AOUT1

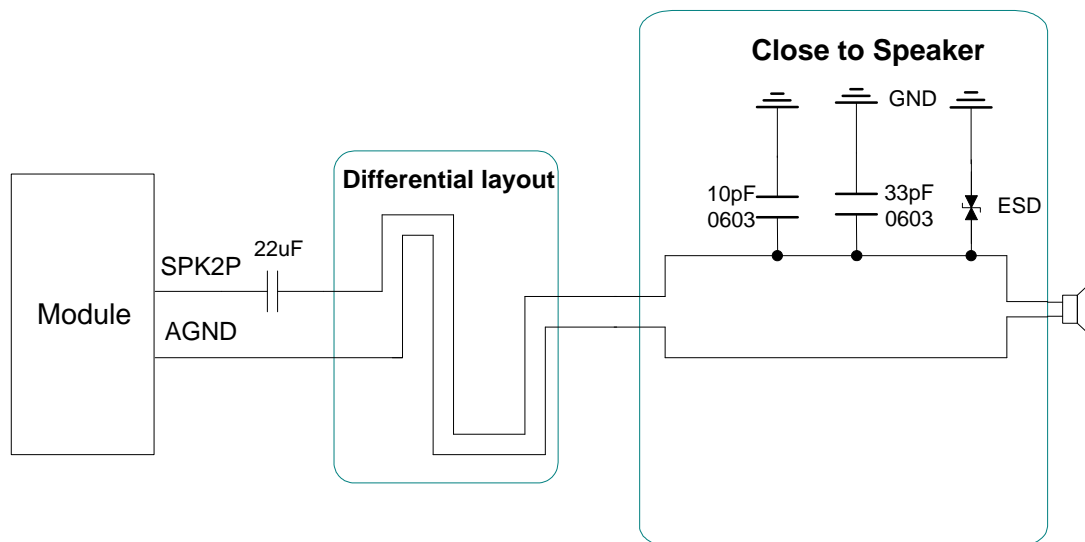


Figure 28: Handset Interface Design for AOUT2

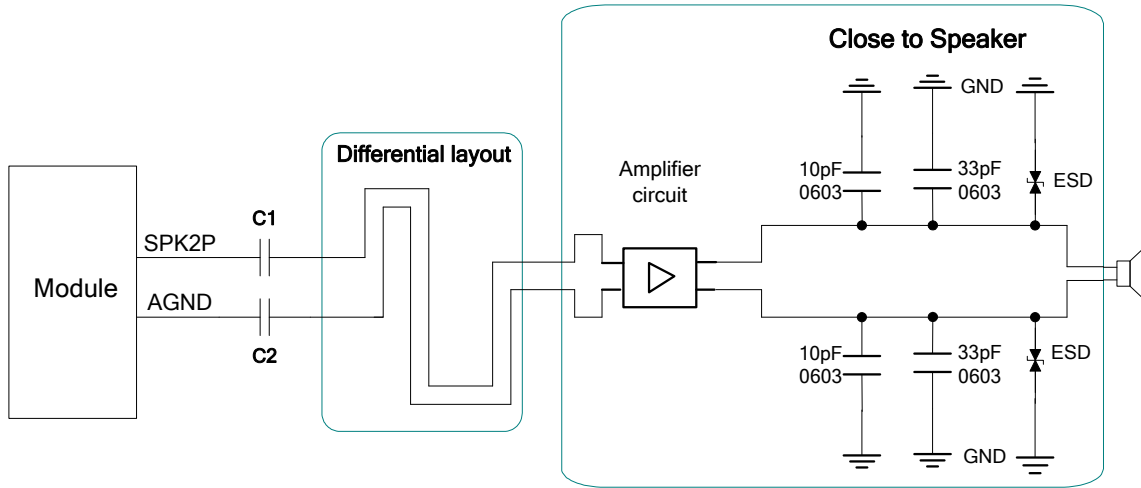


Figure 29: Speaker Interface Design with an Amplifier for AOUT2

The suitable differential audio amplifier can be chosen from the Texas Instrument's website (<http://www.ti.com/>). There are other excellent audio amplifier vendors in the market too.

NOTE

The value of C1 and C2 here depends on the input impedance of audio amplifier.

3.8.4. Earphone Interface Design

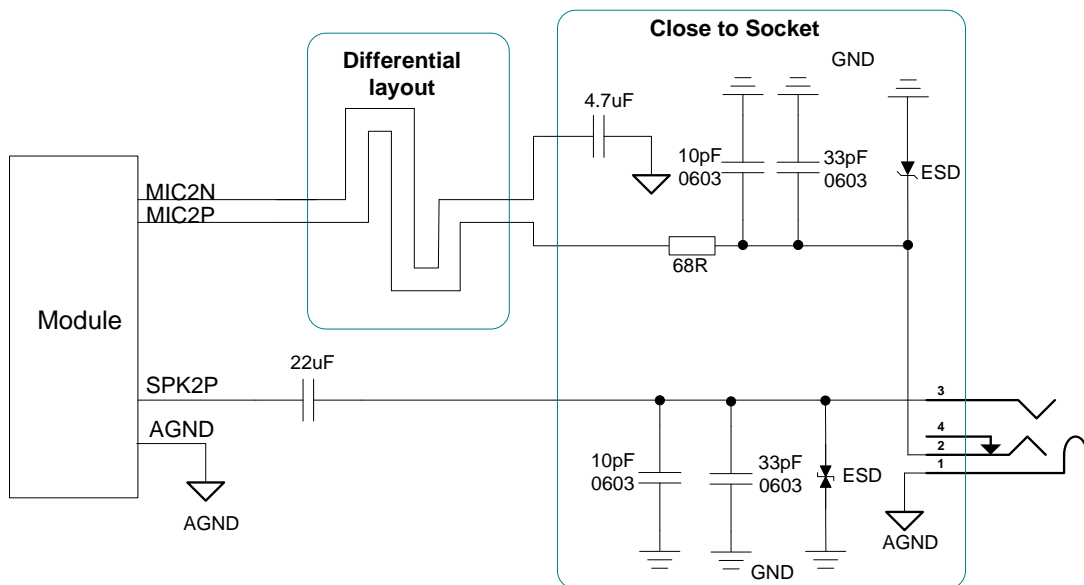


Figure 30: Earphone Interface Design

3.8.5. Loud Speaker Interface Design

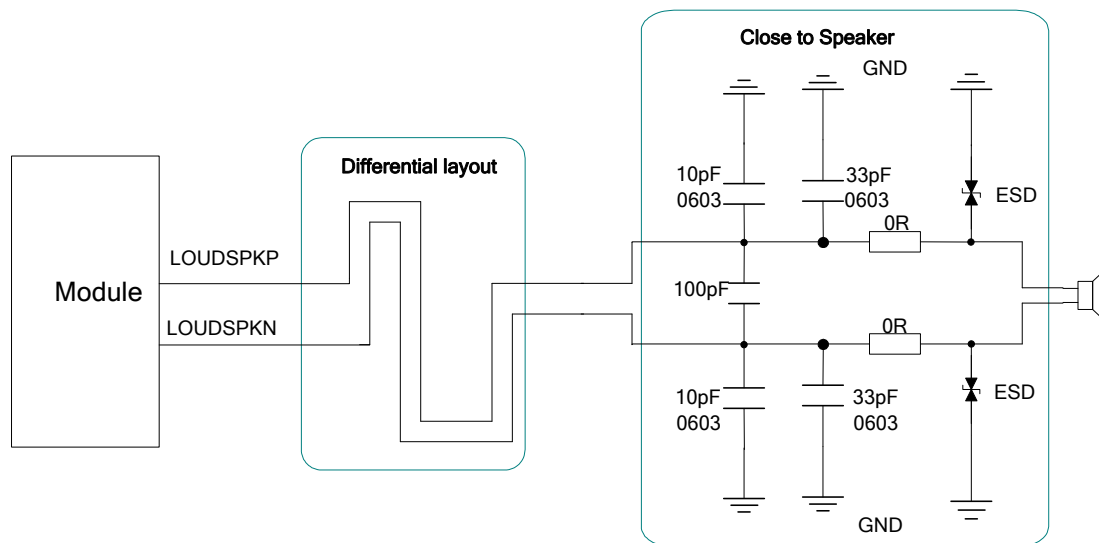


Figure 31: Loud Speaker Interface Design

3.8.6. Audio Characteristics

Table 10: Typical Electret Microphone Characteristics

Parameter	Min.	Typ.	Max.	Unit
Working Voltage	1.2	1.5	2.0	V
Working Current	200		500	uA
External Microphone Load Resistance		2.2		kΩ

Table 11: Typical Speaker Characteristics

Parameter	Min.	Typ.	Max.	Unit
AOUT1 Output	Single-ended	Load resistance	32	Ohm
		Ref level	0	2.4
	Differential	Load resistance	32	Ohm
		Ref level	0	4.8

AOUT2 Output	Single-ended	Load resistance		32	Ohm
		Ref level	0	2.4	V _{pp}
AOUT3 Output	Differential	Load resistance		8	Ohm
		Ref level	0	2×VBAT	V _{pp}

3.9. SIM Card Interfaces

The module contains two SIM interfaces to allow module access the two SIM cards. Only one SIM card can work at a time. Both of two SIM interfaces share the ground and only first SIM interface have card insert detection.

In dual SIM card mode, configure **AT+QDSIM=0** to use the SIM1 interface and configure **AT+QDSIM=1** to use SIM2 interface. For more details, please refer to the **document [1]**.

The SIM interface supports the functionality of the GSM Phase 1 specification and also supports the functionality of the new GSM Phase 2+ specification for FAST 64 kbps SIM card, which is intended for use with a SIM application Tool-kit.

The SIM interface is powered by an internal regulator in the module. Both 1.8V and 3.0V SIM Cards are supported.

Table 12: Pin Definition of the SIM Interface

Pin Name	Pin No.	Description
SIM1_VDD	56	Supply power for SIM card. Automatic detection of SIM card voltage. 3.0V±10% and 1.8V±10%. Maximum supply current is around 10mA.
SIM2_VDD	71	
SIM1_CLK	55	SIM card clock
SIM2_CLK	72	
SIM1_DATA	54	SIM card data I/O
SIM2_DATA	73	
SIM1_RST	53	SIM card reset
SIM2_RST	74	

SIM1_PRESENCE	57	SIM1 card detection
SIM_GND	52	SIM card ground

The following figure is the reference design for SIM interface, and here an 8-pin SIM card holder is used.

The pin SIM1_PRESENCE is used to detect whether the tray of the Molex SIM socket, which is used for holding SIM card, is present in the card socket. When the tray is inserted in the socket, SIM1_PRESENCE is at low level. Regardless of the SIM card is in the tray or not, the change of SIM1_PRESENCE level from high to low level prompts the module to reinitialize SIM card. In default configuration, SIM card detection function is disabled. Your application can use **AT+QSIMDET=1,0** and **AT+QSIMDET=0,0** to switch on and off the SIM card detection function. For details of this AT command, please refer to **document [1]**. When **AT+QSIMDET=1,0** is set and the tray with SIM card is removed from SIM socket, the following URC will be presented:

+CPIN: NOT INSERTED

When the tray with SIM card is inserted into SIM socket again and the module finishes reinitializing SIM card, the following URC will be presented:

+CPIN: READY

Call Ready

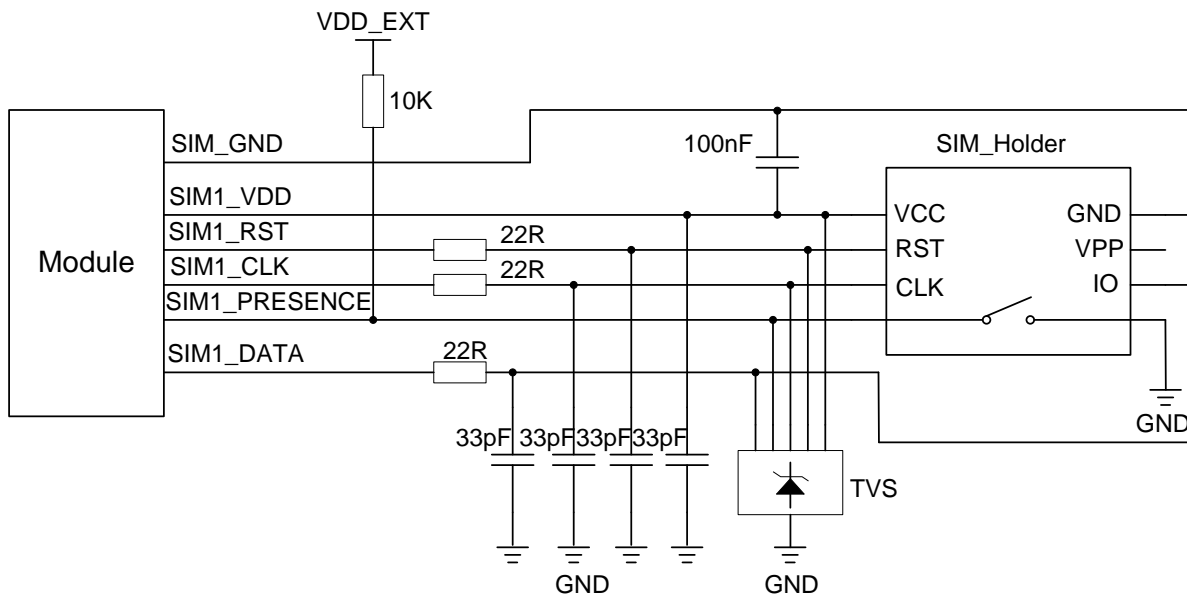


Figure 32: Reference Circuit for SIM1 Interface with 8-pin SIM Card Holder

If the SIM1 card detection function is not used, keep SIM1_PRESENCE pin open. The reference circuit for a 6-pin SIM card socket is illustrated as the following figure.

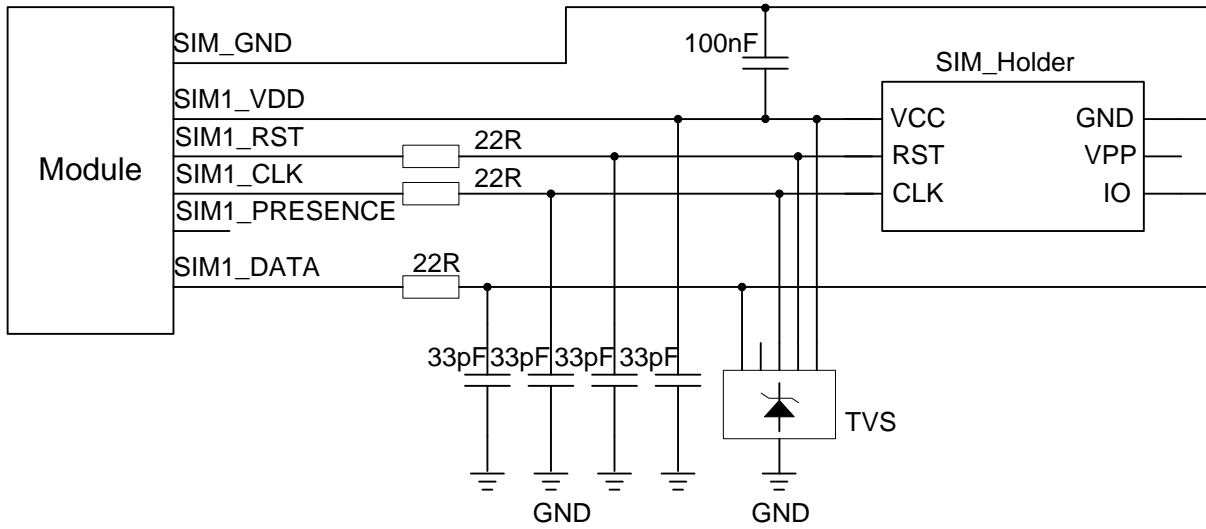


Figure 33: Reference Circuit for SIM1 Interface with the 6-pin SIM Card Holder

The following figure is the reference design for SIM2 interface with the 6-pin SIM card holder.

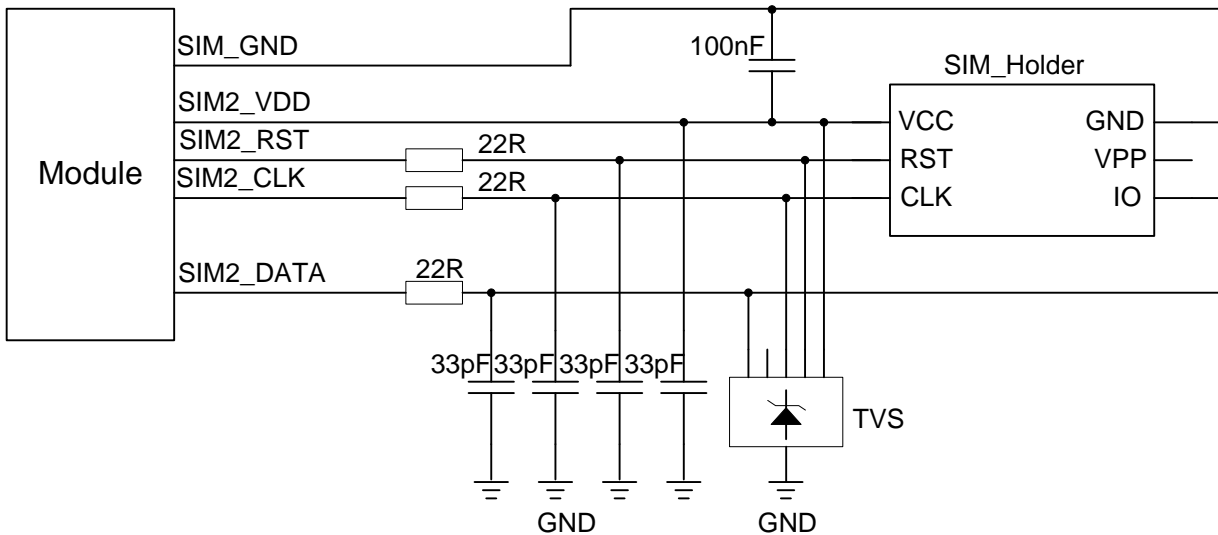


Figure 34: Reference Circuit for SIM2 Interface with the 6-pin SIM Card Holder

For more information of SIM card holder, please visit <http://www.amphenol.com> and <http://www.molex.com>.

In order to enhance the reliability and availability of the SIM card in application. Please follow the below criteria in the SIM circuit design:

- Keep layout of SIM card as close as possible to the module. Assure the length of the trace as less than 200mm as possible.
- Keep SIM card signals away from RF and VBAT alignment.
- Assure the ground between module and SIM cassette short and wide. Keep the width of ground no less than 0.5mm to maintain the same electric potential. The decouple capacitor of SIM_VDD is less than 1uF and must be near to SIM cassette.
- To avoid cross talk between SIM_DATA and SIM_CLK. Keep them away with each other and shield them with surrounded ground.
- In order to offer good ESD protection, it is recommended to add a TVS diode array. For more information of TVS diode, please visit <http://www.onsemi.com/>. The most important rule is to place the ESD protection device close to the SIM card socket and make sure the nets being protected will go through the ESD device first and then lead to module. The 22Ω resistors should be connected in series between the module and the SIM card so as to suppress the EMI spurious transmission and enhance the ESD protection. Please to be noted that the SIM peripheral circuit should be close to the SIM card socket.
- Place the RF bypass capacitors (33pF) close to the SIM card on all signal lines for improving EMI.

3.10. SD Card Interface

The module provides SD card interface that supports many types of memory, such as Memory Stick, SD/MCC card and T-Flash or Micro SD card. The following are the main features of SD card interface.

- Only supports 1bit serial mode.
- Not support the SPI mode for SD memory card.
- Not support multiple SD memory cards.
- Not support hot plug.
- The data rate up to 48MHz in serial mode.
- Up to 32GB maximum memory card capacity.

With the SD card interface features and reference circuit shown as below, you can easily design the SD card application circuit to enhance the memory capacity of the module. The users can store some high-capacity files to external memory card. Such as in the automotive application system, the module can record and store the audio file to the SD card, and also can play the audio files in SD card.

Table 13: Pin Definition of the SD Card Interface

Pin Name	Pin No.	Description
SD_CMD	34	Command signal of SD card output
SD_CLK	35	Clock signal of SD card output
SD_DATA0	36	Data output and input signal of SD card

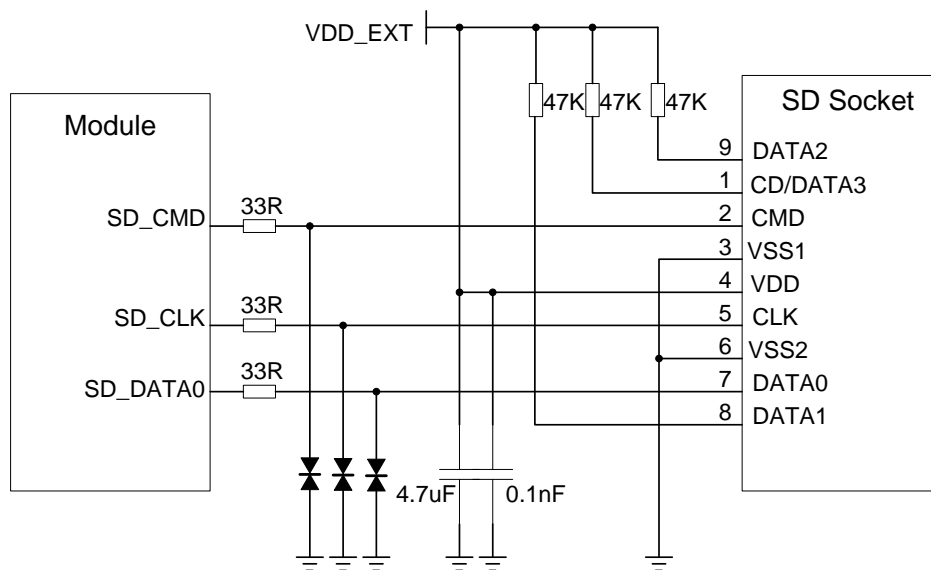


Figure 35: Reference Circuit for SD Card

Table 14: Pin Definition of the SD Card Interface

Pin No.	Pin Name of SD Card	Pin Name of T-Flash (Micro SD) Card
1	CD/DATA3	DATA2
2	CMD	CD/DATA3
3	VSS1	CMD
4	VDD	VDD
5	CLK	CLK
6	VSS2	VSS
7	DATA0	DATA0

8	DATA1	DATA1
9	DATA2	

In SD card interface designing, in order to ensure good communication performance with SD card, the following design principles should be complied with:

- Keep all the SD card signals far away from VBAT power and RF trace.
- Route all SD card signals as short as possible. Ensure the length of every trace does not exceed 10cm.
- The SD_CLK, SD_DATA0 and SD_CMD trace should be routed together. Keep trace difference of SD_DATA0, SD_CMD and SD_CLK to be less than 10mm.
- In order to offer good ESD protection, it is recommended to add TVS on signals with the capacitance less than 15pF.
- Reserve external pull-up resistors for other data lines except the DATA0 signal.
- The SD_CLK and SD_DATA0 line must be shielded by ground in order to improve EMI.

3.11. PCM Interface

M85 supports PCM interface. It is used for digital audio transmission between the module and the device. This interface is composed of PCM_CLK, PCM_SYNC, PCM_IN and PCM_OUT signal lines.

Pulse-code modulation (PCM) is a converter that changes the consecutive analog audio signal to discrete digital signal. The whole procedure of Pulse-code modulation contains sampling, quantizing and encoding.

Table 15: Pin Definition of PCM Interface

Pin Name	Pin No.	Description
PCM_IN	18	PCM data input
PCM_CLK	19	PCM clock output
PCM_OUT	20	PCM data output
PCM_SYNC	21	PCM frame synchronization output

3.11.1. Configuration

M85 module supports 13-bit line code PCM format. The sample rate is 8 KHz, and the clock source is 256 KHz, and the module can only act as master mode. The PCM interface supports both long and short synchronization simultaneously. Furthermore, it only supports MSB first. For detailed information, please refer to the table below.

Table 16: Configuration

PCM	
Line Interface Format	Linear
Data Length	Linear: 13 bits
Sample Rate	8KHz
PCM Clock/Synchronization Source	PCM master mode: clock and synchronization is generated by module
PCM Synchronization Rate	8KHz
PCM Clock Rate	PCM master mode: 256 KHz (line)
PCM Synchronization Format	Long/short synchronization
PCM Data Ordering	MSB first
Zero Padding	Yes
Sign Extension	Yes

3.11.2. Timing

The sample rate of the PCM interface is 8 KHz and the clock source is 256 KHz, so every frame contains 32 bits data, since M85 supports 16 bits line code PCM format, the left 16 bits are invalid. The following diagram shows the timing of different combinations. The synchronization length in long synchronization format can be programmed by firmware from one bit to eight bits. In the Sign extension mode, the high three bits of 16 bits are sign extension, and in the Zero padding mode, the low three bits of 16 bits are zero padding.

Under zero padding mode, you can configure the PCM input and output volume by executing **AT+QPCMVOL** command. For more details, please refer to **Chapter 3.11.4**.

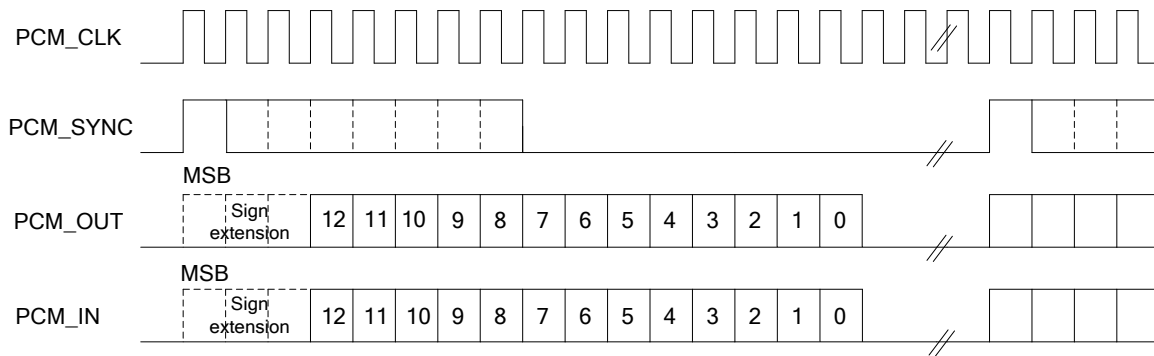


Figure 36: Long Synchronization & Sign Extension Diagram

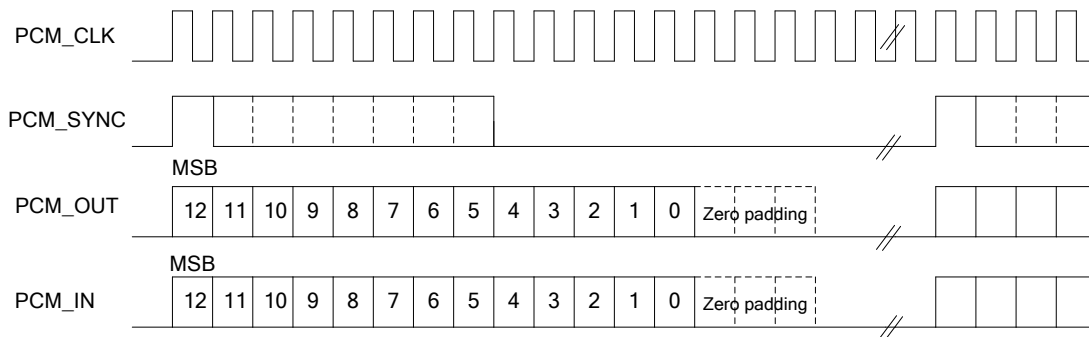


Figure 37: Long Synchronization & Zero Padding Diagram

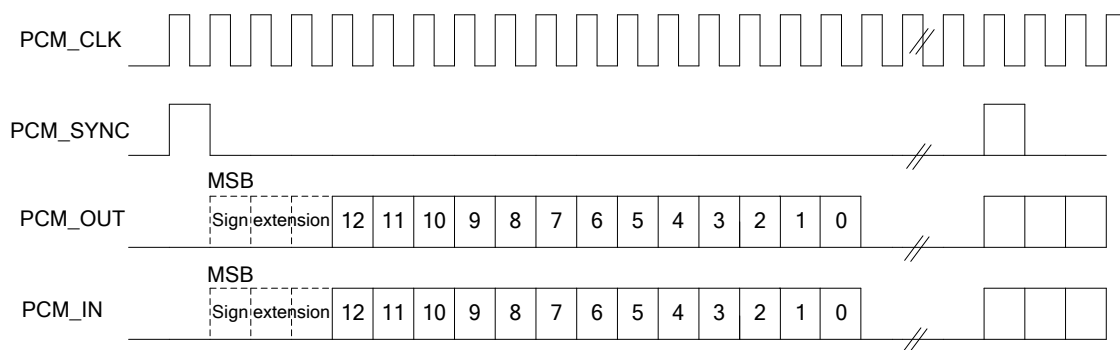


Figure 38: Short synchronization & Sign Extension Diagram

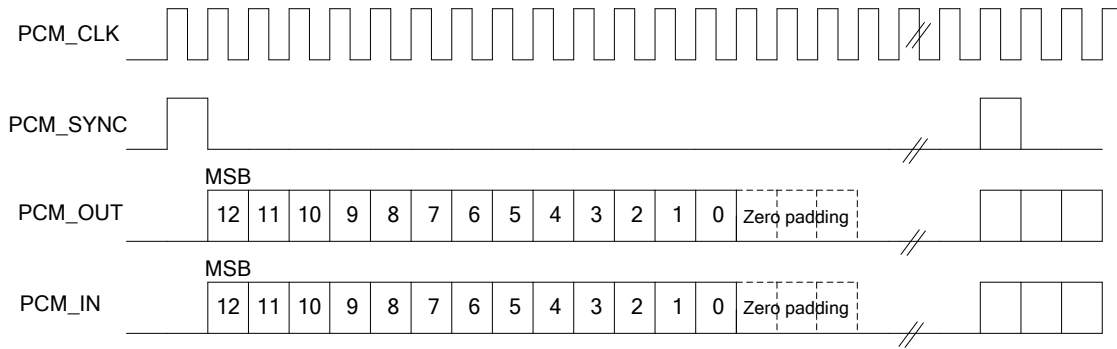


Figure 39: Short Synchronization & Zero Padding Diagram

3.11.3. Reference Design

M85 can only work as a master, providing synchronization and clock source. The reference design is shown as below.

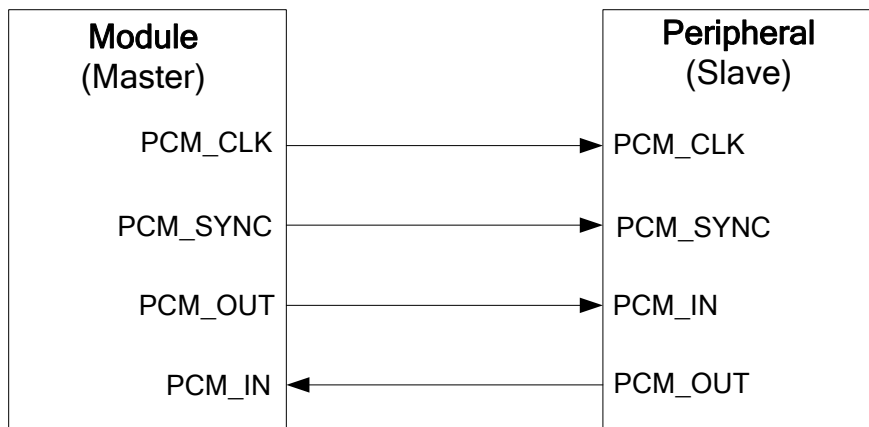


Figure 40: Reference Design for PCM

3.11.4. AT Command

There are two AT commands about the configuration of PCM are listed as below.

AT+QPCMON can configure operating mode of PCM.

AT+QPCMON= mode,Sync_Type,Sync_Length,SignExtension,MSBFirst.

Table 17: QPCMON Command Description

Parameter	Scope	Description
Mode	0~2	0: Close PCM 1: Open PCM 2: Open PCM when audio talk is set up
Sync_Type	0~1	0: Short synchronization 1: Long synchronization
Sync_Length	1~8	Programmed from one bit to eight bit
SignExtension	0~1	0: Zero padding 1: Sign extension
MSBFirst	0~1	0: MSB first 1: Not supported

AT+QPCMVOL can configure the volume of input and output.

AT+QPCMVOL=vol_pcm_in, vol_pcm_out

Table 18: QPCMVOL Command Description

Parameter	Scope	Description
vol_pcm_in	0~32767	Set the input volume
vol_pcm_out	0~32767	Set the output volume The voice may be distorted when this value exceeds 16384.

3.12. ADC

The module provides an ADC channel to measure the value of voltage. Please give priority to the use of ADC0 channel. The command **AT+QADC** can read the voltage value applied on ADC0 pin. For details of this AT command, please refer to the **document [1]**. In order to improve the accuracy of ADC, the layout of ADC should be surrounded by ground.

Table 19: Pin Definition of the ADC

Pin Name	Pin No.	Description
ADC0	2	Analog to digital converter.

Table 20: Characteristics of the ADC

Item	Min.	Typ.	Max.	Units
Voltage Range	0		2.8	V
ADC Resolution		10		bits
ADC Accuracy		2.7		mV

3.13. Behaviors Of The RI

Table 21: Behaviors of the RI

State	RI response
Standby	HIGH
Voice Calling	Change to LOW, then: <ol style="list-style-type: none"> Change to HIGH when call is established. Use ATH to hang up the call, RI changes to HIGH. Calling part hangs up, RI changes to HIGH first, and changes to LOW for 120ms indicating "NO CARRIER" as an URC, then changes to HIGH again. Change to HIGH when SMS is received.
SMS	When a new SMS comes, the RI changes to LOW and holds low level for about 120 ms, then changes to HIGH.
URC	Certain URCs can trigger 120ms low level on RI.

NOTE

If URC of SMS is disabled, the RI will not change.

If the module is used as a caller, the RI would maintain high except the URC or SMS is received. On the other hand, when it is used as a receiver, the timing of the RI is shown as below.

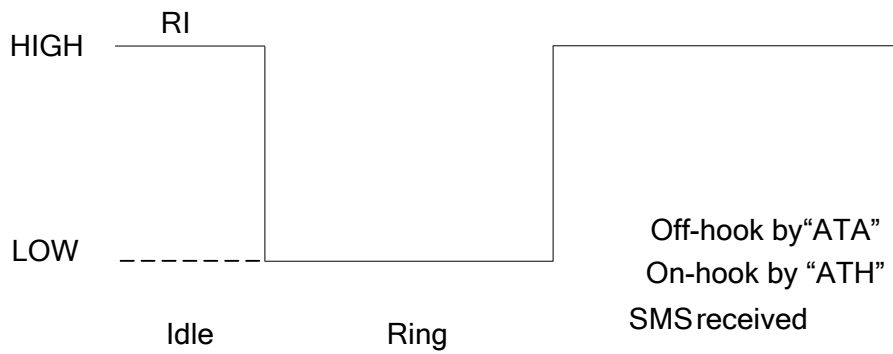


Figure 41: RI Behavior of Voice Calling as a Receiver

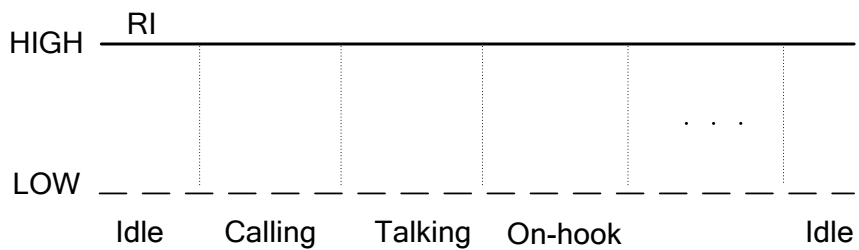


Figure 42: RI Behavior as a Caller

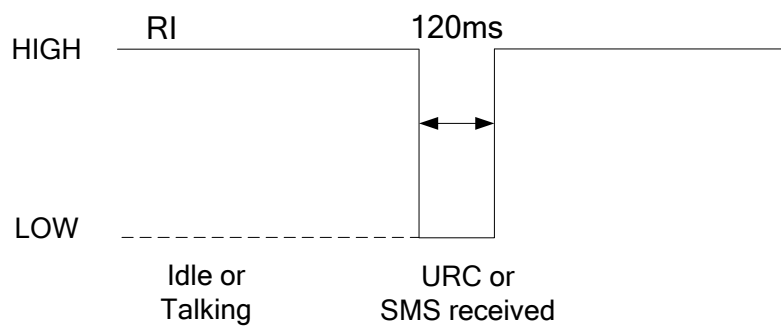


Figure 43: RI Behavior of URC or SMS Received

3.14. Network Status Indication

The NETLIGHT signal can be used to drive a network status indicator LED. The working state of this pin is listed in the following table.

Table 22: Working State of the NETLIGHT

State	Module function
Off	The module is not running.
64ms On/800ms Off	The module is not synchronized with network.
64ms On/2000ms Off	The module is synchronized with network.
64ms On/600ms Off	The GPRS data transmission after dialing the PPP connection.

A reference circuit is shown as below.

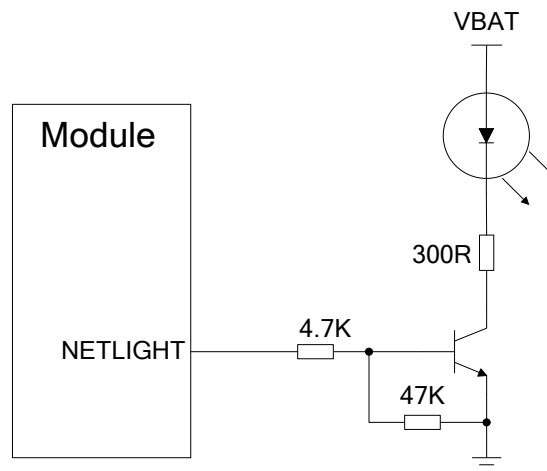


Figure 44: Reference Design for NETLIGHT

3.15. Operating Status Indication

The STATUS pin will output a high level after the module being turned on, but it is not recommended connecting this pin to a MCU's GPIO to judge whether the module is turn-on or not. The following LED indicator circuit for STATUS pin can be used to indicate the state after the module has been turned on.

Table 23: Pin Definition of the STATUS

Pin Name	Pin No.	Description
STATUS	16	Indicate module operating status

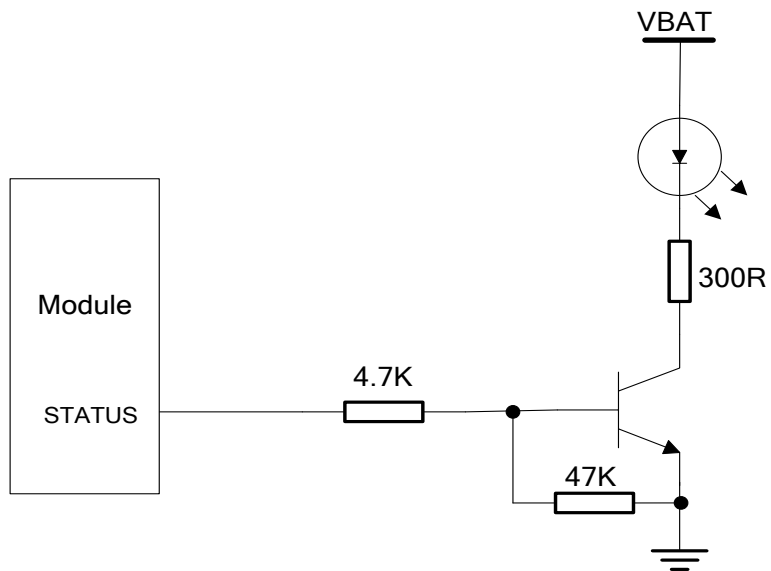


Figure 45: Reference Design for STATUS

4 Antenna Interface

The Pin 63 is the RF antenna pad. The RF interface has an impedance of 50Ω.

Table 24: Pin Definition of the RF_ANT

Pin Name	Pin No.	Description
GND	61	Ground
GND	62	Ground
RF_ANT	63	RF antenna pad
GND	64	Ground
GND	65	Ground
GND	66	Ground

4.1. Reference Design

The external antenna must be matched properly to achieve best performance, so the matching circuit is necessary, the reference design for RF is shown as below.

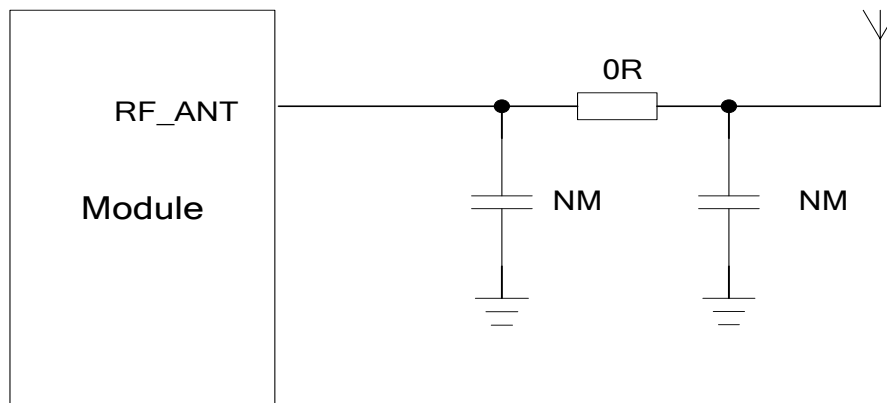


Figure 46: Reference Design for RF

M85 provides an RF antenna pad for antenna connection. The RF trace in host PCB connected to the module RF antenna pad should be coplanar waveguide line or microstrip line, whose characteristic impedance should be close to 50Ω. M85 comes with grounding pads which are next to the antenna pad in order to give a better grounding. Besides, a π type match circuit is suggested to be used to adjust the RF performance.

4.2. RF Output Power

Table 25: The Module Conducted RF Output Power

Frequency	Max.	Min.
GSM850	33dBm±2dB	5dBm±5dB
EGSM900	33dBm±2dB	5dBm±5dB
DCS1800	30dBm±2dB	0dBm±5dB
PCS1900	30dBm±2dB	0dBm±5dB

NOTE

In GPRS 4 slots TX mode, the max output power is reduced by 2.5dB. This design conforms to the GSM specification as described in **Section 13.16** of **3GPP TS 51.010-1**.

4.3. RF Receiving Sensitivity

Table 26: The Module Conducted RF Receiving Sensitivity

Frequency	Receive Sensitivity
GSM850	< -109dBm
EGSM900	< -109dBm
DCS1800	< -109dBm
PCS1900	< -109dBm

4.4. Operating Frequencies

Table 27: The Module Operating Frequencies

Frequency	Receive	Transmit	ARFCH
GSM850	869~894MHz	824~849MHz	128~251
EGSM900	925~960MHz	880~915MHz	0~124, 975~1023
DCS1800	1805~1880MHz	1710~1785MHz	512~885
PCS1900	1930~1990MHz	1850~1910MHz	512~810

4.5. Antenna Requirement

The following table shows the requirement on GSM antenna.

Table 28: Antenna Cable Requirements

Type	Requirements
GSM850/EGSM900	Cable insertion loss <1dB
DCS1800/PCS1900	Cable insertion loss <1.5dB

Table 29: Antenna Requirements

Type	Requirements
Frequency Range	GSM850/EGSM900/DCS1800/PCS1900MHz.
VSWR	≤ 2
Gain (dBi)	1
Max Input Power (W)	50
Input Impedance (Ω)	50
Polarization Type	Vertical

4.6. RF Cable Soldering

Soldering the RF cable to RF pad of module correctly will reduce the loss on the path of RF, please refer to the following example of RF soldering.

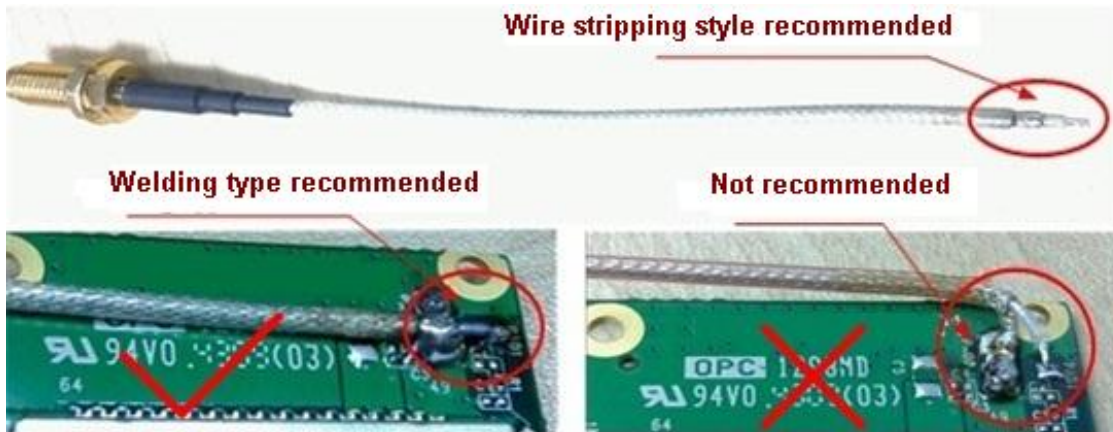


Figure 47: RF Soldering Sample

5 Electrical, Reliability and Radio Characteristics

5.1. Absolute Maximum Ratings

Absolute maximum ratings for power supply and voltage on digital and analog pins of module are listed in the following table:

Table 30: Absolute Maximum Ratings

Parameter	Min.	Max.	Unit
V _{BAT}	-0.3	+4.73	V
Peak current of power supply	0	2	A
RMS current of power supply (during one TDMA- frame)	0	0.7	A
Voltage at digital pins	-0.3	3.08	V
Voltage at analog pins	-0.3	3.08	V
Voltage at digital/analog pins in power down mode	-0.25	0.25	V

5.2. Operating Temperature

The operating temperature is listed in the following table:

Table 31: Operating Temperature

Parameter	Min.	Typ.	Max.	Unit
Normal Temperature	-35	+25	+80	°C
Restricted Operation ¹⁾	-40 ~ -35		+80 ~ +85	°C
Storage Temperature	-45		+90	°C

NOTE

¹⁾When the module works within this temperature range, the deviation from the GSM specification may occur. For example, the frequency error or the phase error will be increased.

5.3. Power Supply Ratings

Table 32: The Module Power Supply Ratings

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
VBAT	Supply voltage	Voltage must stay within the min/max values, including voltage drop, ripple, and spikes.	3.3	4.0	4.6	V
	Voltage drop during transmitting burst	Maximum power control level on GSM850 and EGSM900.			400	mV
I _{VBAT}	Average supply current	Power down mode		150		uA
		SLEEP mode @DRX=5		1.3		mA
		Minimum functionality mode AT+CFUN=0				
		IDLE mode		13		mA
		SLEEP mode		0.98		mA

AT+CFUN=4				
	IDLE mode	13		mA
	SLEEP mode	1.0		mA
TALK mode				
	GSM850/EGSM900 ¹⁾	223/219		mA
	DCS1800/PCS1900 ²⁾	153/151		mA
DATA mode, GPRS (3Rx,2Tx)				
	GSM850/EGSM900 ¹⁾	363/393		mA
	DCS1800/PCS1900 ²⁾	268/257		mA
DATA mode, GPRS (2Rx,3Tx)				
	GSM850/EGSM900 ¹⁾	506/546		mA
	DCS1800/PCS1900 ²⁾	366/349		mA
DATA mode, GPRS (4Rx,1Tx)				
	GSM850/EGSM900 ¹⁾	217/234		mA
	DCS1800/PCS1900 ²⁾	172/170		mA
DATA mode, GPRS (1Rx,4Tx)				
	GSM850/EGSM900 ¹⁾	458/485 ³⁾		mA
	DCS1800/PCS1900 ²⁾	462/439		mA
Peak supply current (during transmission slot)	Maximum power control level on GSM850 and EGSM900.	1.6	2	A

NOTES

- ¹⁾ Power control level PCL 5.
- ²⁾ Power control level PCL 0.
- ³⁾ Under the GSM850 and EGSM900 spectrum, the power of 1Rx and 4Tx has been reduced.

5.4. Current Consumption

The values of current consumption are shown as below.

Table 33: The Module Current Consumption

Condition	Current Consumption
Voice Call	
GSM850	@power level #5 <300mA, Typical 223mA

	@power level #12, Typical 83mA @power level #19, Typical 62mA
EGSM900	@power level #5 <300mA, Typical 219mA @power level #12, Typical 83mA @power level #19, Typical 63mA
DCS1800	@power level #0 <250mA, Typical 153mA @power level #7, Typical 73mA @power level #15, Typical 60mA
PCS1900	@power level #0 <250mA, Typical 151mA @power level #7, Typical 76mA @power level #15, Typical 61mA

GPRS Data

DATA Mode, GPRS (3Rx, 2Tx) CLASS 12

GSM850	@power level #5 <550mA, Typical 363mA @power level #12, Typical 131mA @power level #19, Typical 91mA
EGSM900	@power level #5 <550mA, Typical 393mA @power level #12, Typical 132mA @power level #19, Typical 92mA
DCS1800	@power level #0 <450mA, Typical 268mA @power level #7, Typical 112mA @power level #15, Typical 88mA
PCS1900	@power level #0 <450mA, Typical 257mA @power level #7, Typical 119mA @power level #15, Typical 89mA

DATA Mode, GPRS (2Rx, 3Tx) CLASS 12

GSM850	@power level #5 <640mA, Typical 506mA @power level #12, Typical 159mA @power level #19, Typical 99mA
EGSM900	@power level #5 <600mA, Typical 546mA @power level #12, Typical 160mA @power level #19, Typical 101mA
DCS1800	@power level #0 <490mA, Typical 366mA @power level #7, Typical 131mA @power level #15, Typical 93mA
PCS1900	@power level #0 <480mA, Typical 348mA @power level #7, Typical 138mA @power level #15, Typical 94mA

DATA Mode, GPRS (4Rx, 1Tx) CLASS 12

GSM850	@power level #5 <350mA, Typical 216mA @power level #12, Typical 103mA @power level #19, Typical 83mA
EGSM900	@power level #5 <350mA, Typical 233mA @power level #12, Typical 104mA @power level #19, Typical 84mA
DCS1800	@power level #0 <300mA, Typical 171mA @power level #7, Typical 96mA @power level #15, Typical 82mA
PCS1900	@power level #0 <300mA, Typical 169mA @power level #7, Typical 98mA @power level #15, Typical 83mA
DATA Mode, GPRS (1Rx, 4Tx) CLASS 12	
GSM850	@power level #5 <660mA, Typical 457mA @power level #12, Typical 182mA @power level #19, Typical 106mA
EGSM900	@power level #5 <660mA, Typical 484mA @power level #12, Typical 187mA @power level #19, Typical 109mA
DCS1800	@power level #0 <530mA, Typical 461mA @power level #7, Typical 149mA @power level #15, Typical 97mA
PCS1900	@power level #0 <530mA, Typical 439mA @power level #7, Typical 159mA @power level #15, Typical 99mA

NOTE

GPRS Class 12 is the default setting. The module can be configured from GPRS Class 1 to Class 12. Setting to lower GPRS class would make it easier to design the power supply for the module.

5.5. Electro-static Discharge

Although the GSM engine is generally protected against Electro-static Discharge (ESD), ESD protection precautions should still be emphasized. Proper ESD handling and packaging procedures must be applied throughout the processing, handling and operation of any applications using the module.

The measured ESD values of module are shown as the following table:

Table 34: The ESD Endurance (Temperature: 25°C, Humidity: 45%)

Tested Point	Contact Discharge	Air Discharge
VBAT, GND	±5KV	±10KV
RF_ANT	±5KV	±10KV
TXD, RXD	±2KV	±4KV
Others	±0.5KV	±1KV

6 Mechanical Dimensions

This chapter describes the mechanical dimensions of the module.

6.1. Mechanical Dimensions of Module

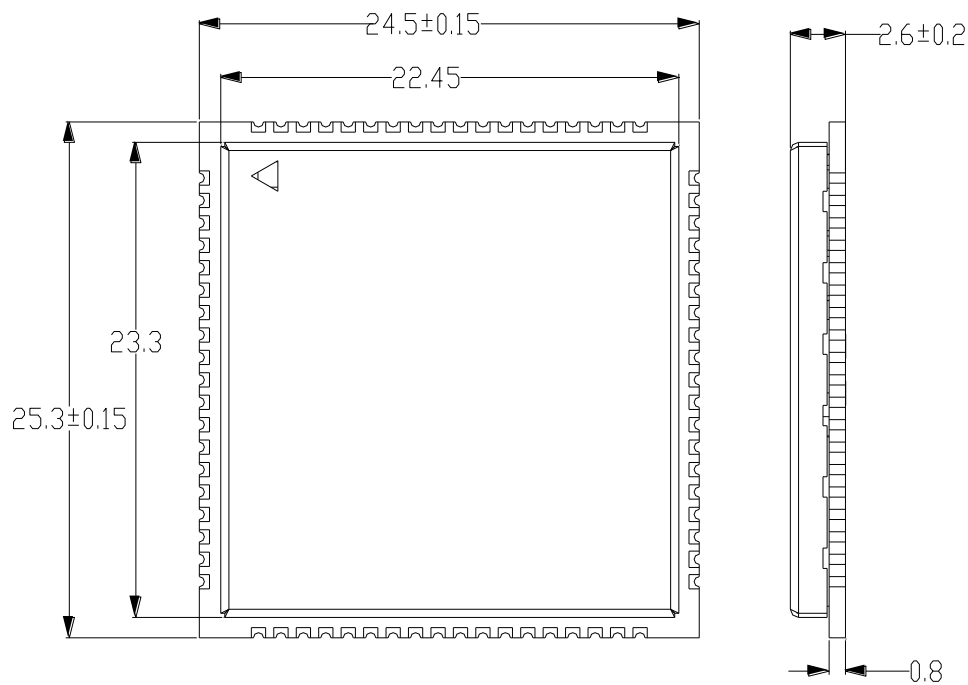


Figure 48: M85 Module Top and Side Dimensions (Unit: mm)

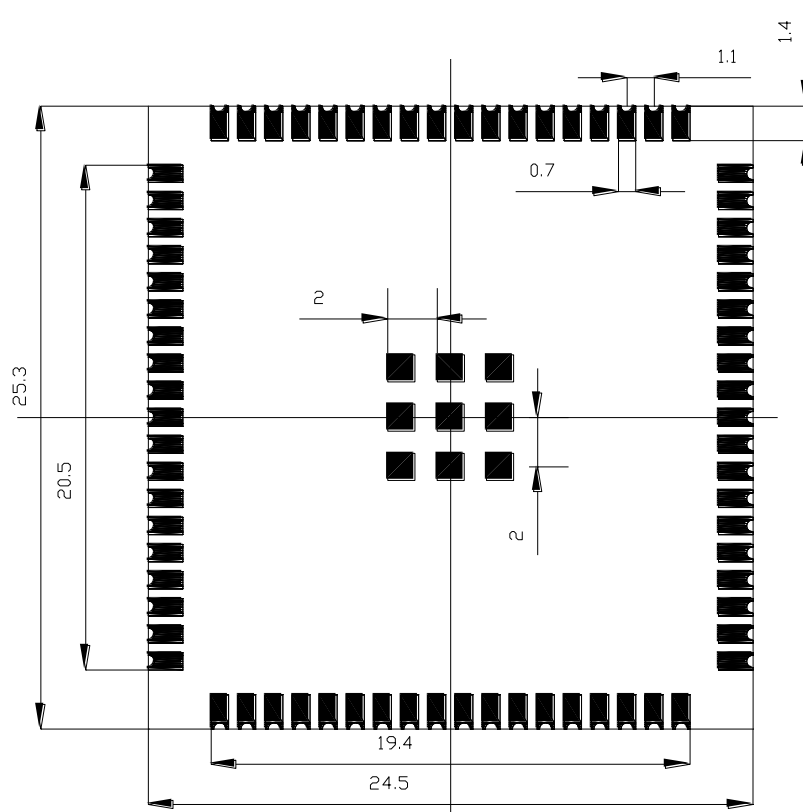


Figure 49: M85 Module Bottom Dimensions (Unit: mm)

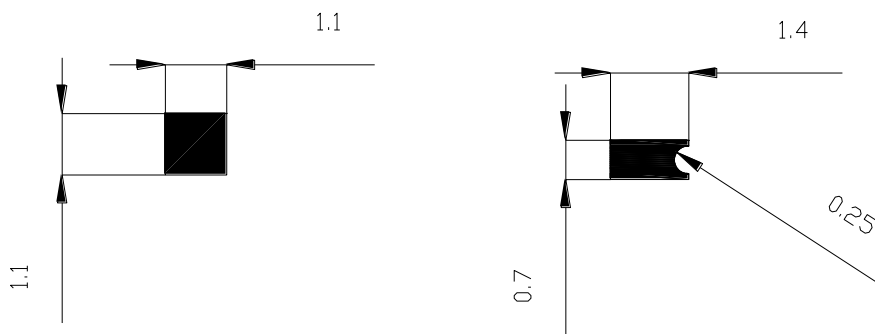


Figure 50: The PAD Dimensions (Unit: mm)

6.2. Recommended Footprint

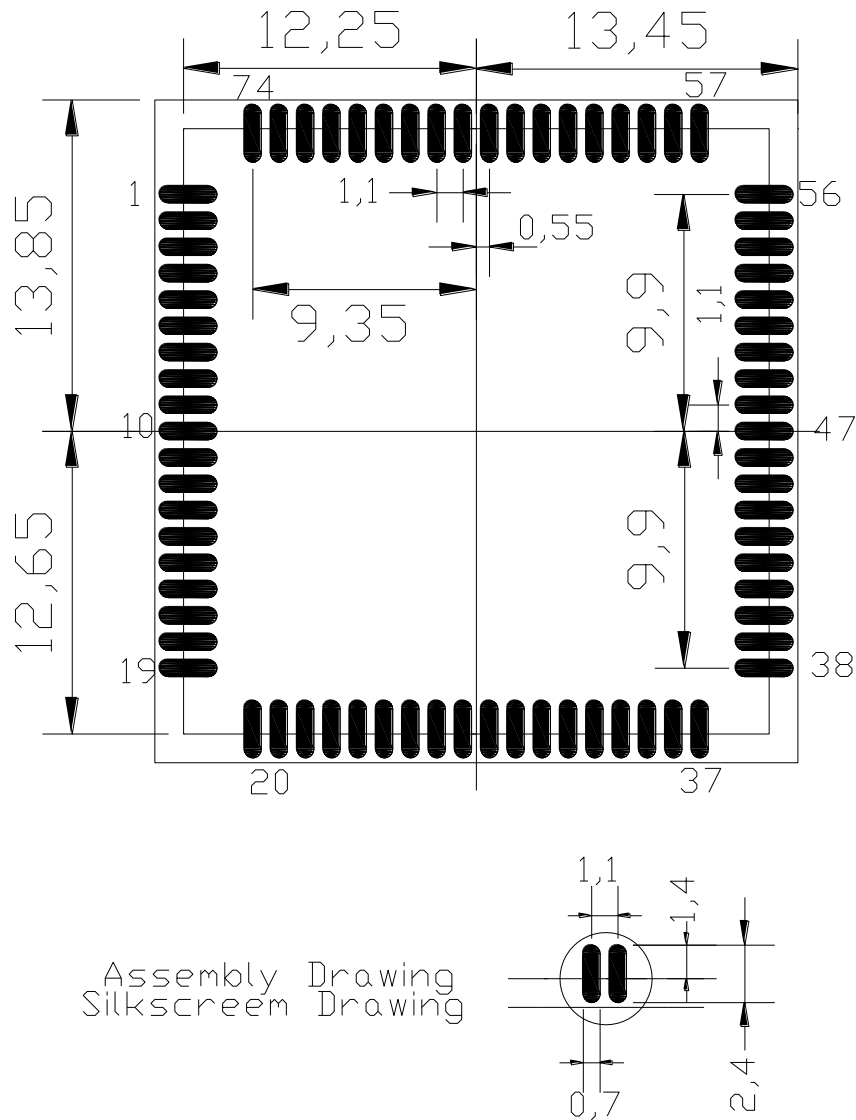


Figure 51: Recommended Footprint (Unit: mm)

NOTE

The module should keep about 3mm away from other components in the host PCB.

6.3. Top View of the Module

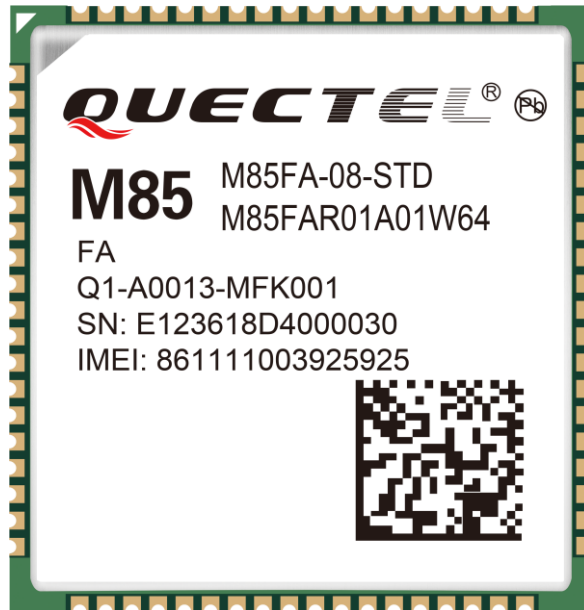


Figure 52: Top View of the Module

6.4. Bottom View of the Module

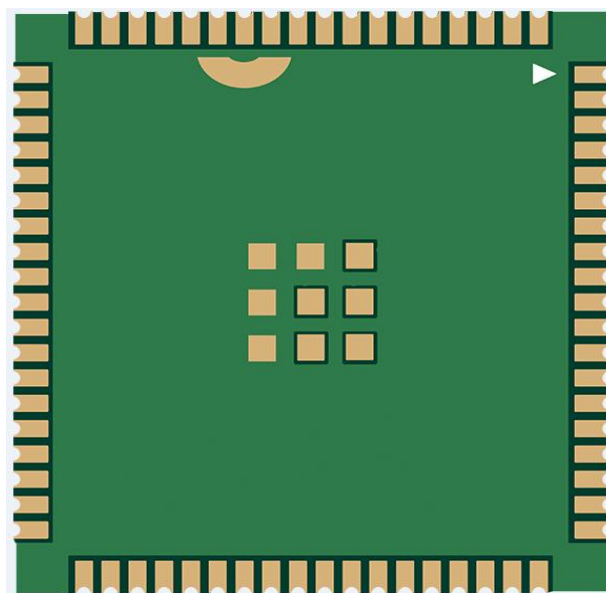


Figure 53: Bottom View of the Module

7 Storage and Manufacturing

7.1. Storage

M85 module is distributed in a vacuum-sealed bag. The restriction for storage is shown as below.

Shelf life in the vacuum-sealed bag: 12 months at environments of $<40^{\circ}\text{C}$ temperature and $< 90\% \text{RH}$.

After the vacuum-sealed bag is opened, devices that need to be mounted directly must be:

- Mounted within 72 hours at the factory environment of $\leq 30^{\circ}\text{C}$ temperature and $<60\% \text{RH}$.
- Stored at $<10\% \text{RH}$.

Devices require baking before mounting, if any circumstance below occurs.

- When the ambient temperature is $23^{\circ}\text{C} \pm 5^{\circ}\text{C}$, humidity indication card shows the humidity is $>10\%$ before opening the vacuum-sealed bag.
- If ambient temperature is $<30^{\circ}\text{C}$ and the humidity is $<60\%$, the devices have not been mounted during 72hours.
- Stored at $>10\% \text{RH}$.

If baking is required, devices should be baked for 48 hours at $125^{\circ}\text{C} \pm 5^{\circ}\text{C}$.

NOTE

As plastic container cannot be subjected to high temperature, devices must be removed prior to high temperature (125°C) bake. If shorter bake times are desired, refer to the IPC/JEDECJ-STD-033 for bake procedure.

7.2. Soldering

The squeegee should push the paste on the surface of the stencil that makes the paste fill the stencil openings and penetrate to the PCB. The force on the squeegee should be adjusted so as to produce a clean stencil surface on a single pass. To ensure the module soldering quality, the thickness of stencil at the hole of the module pads should be 0.2 mm for M85. For more details, please refer to **document [13]**.

It is suggested that peak reflow temperature is from 235°C to 245°C (for SnAg3.0Cu0.5 alloy). Absolute max reflow temperature is 260°C. To avoid damage to the module when it was repeatedly heated, it is suggested that the module should be mounted after the first panel has been reflowed. The following picture is the actual diagram which we have operated.

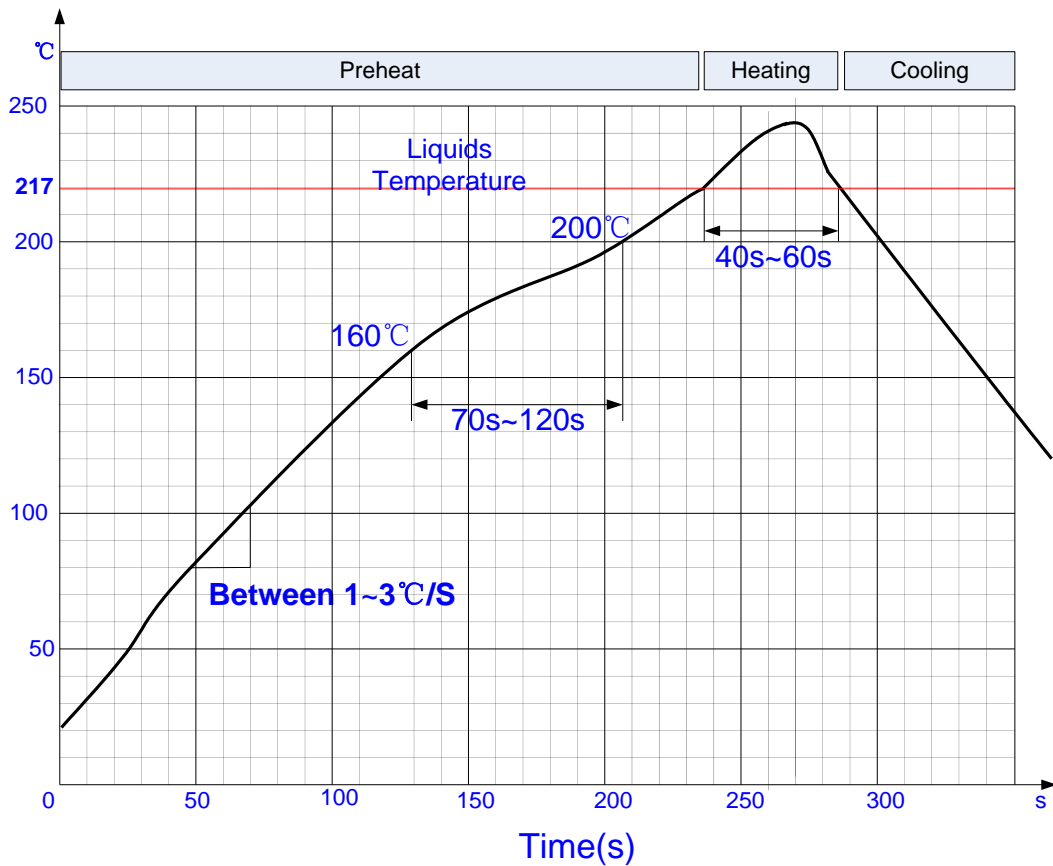
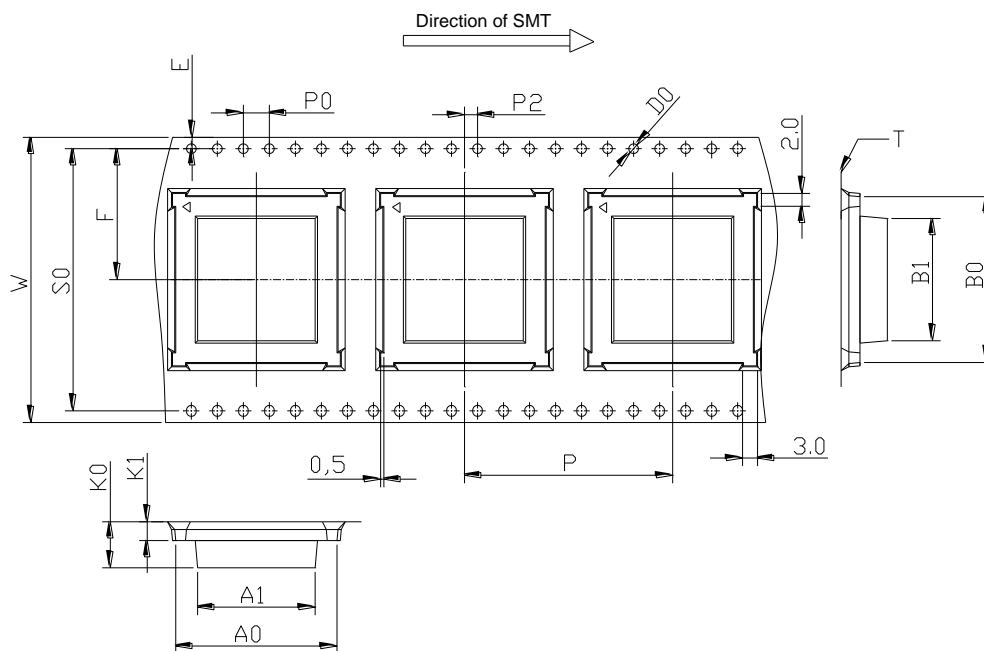


Figure 54: Ramp-Soak-Spike Reflow Profile

7.3. Packaging

M85 modules are shipped in tape and reel form. The reel is 330mm in diameter and each reel contains 250pcs modules. This is especially suitable for the M85 according to SMT assembly processes requirements.

The tape is packed in a vacuum-sealed bag which is ESD protected. Furthermore, it should not be opened until the devices are ready to be soldered onto the application.



W	44.00±0.30	P	32.00±0.10	A0	24.80±0.10	B0	25.60±0.10
S	40.40±0.10	P0	4.00±0.10	A1	18.00±0.10	B1	18.90±0.10
E	1.75±0.10	P2	2.00±0.15				
F	20.20±0.15	D0	$\phi 1.50^{+0.10}_0$	K0	7.10±0.10		
T	0.50±0.05	D1	$\phi 2.00$ MIN	K1	2.90±0.10		

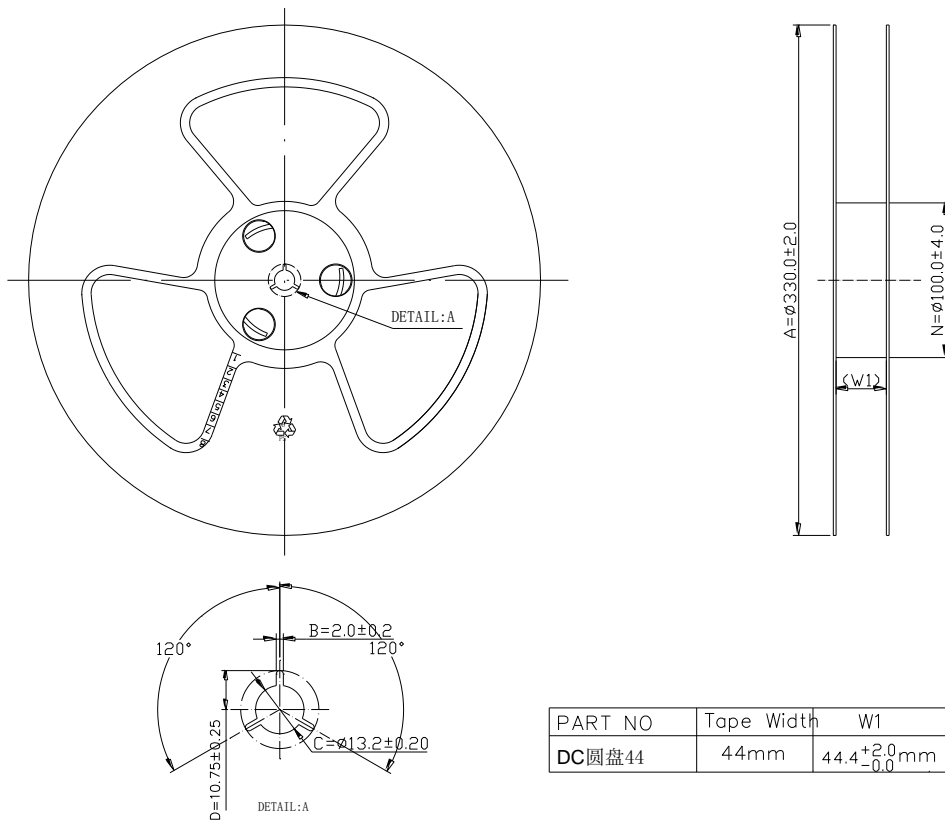


Figure 55: Tape and Reel Information

Table 35: Reel Packing

Model Name	MOQ for MP	Minimum Package: 250pcs	Minimum Package×4=1000pcs
M85	250pcs	Size: 370 × 350 × 56mm N.W: 0.78kg G.W: 1.54kg	Size: 380 × 250 × 365mm N.W: 3.10kg G.W: 6.80kg

8 Appendix A Reference

Table 36: Related Documents

SN	Document Name	Remark
[1]	Quectel_M85_AT_Commands_Manual	AT commands manual
[2]	ITU-T Draft new recommendation V.25ter	Serial asynchronous automatic dialing and control
[3]	GSM 07.07	Digital cellular telecommunications (Phase 2+); AT command set for GSM Mobile Equipment (ME)
[4]	GSM 07.10	Support GSM 07.10 multiplexing protocol
[5]	GSM 07.05	Digital cellular telecommunications (Phase 2+); Use of Data Terminal Equipment – Data Circuit terminating Equipment (DTE – DCE) interface for Short Message Service (SMS) and Cell Broadcast Service (CBS)
[6]	GSM 11.14	Digital cellular telecommunications (Phase 2+); Specification of the SIM Application Toolkit for the Subscriber Identity module – Mobile Equipment (SIM – ME) interface
[7]	GSM 11.11	Digital cellular telecommunications (Phase 2+); Specification of the Subscriber Identity module – Mobile Equipment (SIM – ME) interface
[8]	GSM 03.38	Digital cellular telecommunications (Phase 2+); Alphabets and language-specific information
[9]	GSM 11.10	Digital cellular telecommunications (Phase 2); Mobile Station (MS) conformance specification; Part 1: Conformance specification
[10]	Quectel_GSM_UART_Application_Note	UART port application note
[11]	Quectel_GSM_Module_Digital_IO_Application_Note	GSM Module Digital IO Application Note

[12]	Quectel_GSM_EVB_User_Guide	GSM EVB user guide
[13]	Quectel_Module_Secondary_SMT_User_Guide	Module secondary SMT user guide

Table 37: Terms and Abbreviations

Abbreviation	Description
ADC	Analog-to-Digital Converter
AMR	Adaptive Multi-Rate
ARP	Antenna Reference Point
ASIC	Application Specific Integrated Circuit
BER	Bit Error Rate
BOM	Bill Of Material
BTS	Base Transceiver Station
CHAP	Challenge Handshake Authentication Protocol
CS	Coding Scheme
CSD	Circuit Switched Data
CTS	Clear To Send
DAC	Digital-to-Analog Converter
DRX	Discontinuous Reception
DSP	Digital Signal Processor
DCE	Data Communications Equipment (typically module)
DTE	Data Terminal Equipment (typically computer, external controller)
DTR	Data Terminal Ready
DTX	Discontinuous Transmission
EFR	Enhanced Full Rate
EGSM	Enhanced GSM

EMC	Electromagnetic Compatibility
ESD	Electrostatic Discharge
ETS	European Telecommunication Standard
FCC	Federal Communications Commission (U.S.)
FDMA	Frequency Division Multiple Access
FR	Full Rate
GMSK	Gaussian Minimum Shift Keying
GPRS	General Packet Radio Service
GSM	Global System for Mobile Communications
G.W	Gross Weight
HR	Half Rate
I/O	Input/Output
IC	Integrated Circuit
IMEI	International Mobile Equipment Identity
Imax	Maximum Load Current
Inorm	Normal Current
kbps	Kilo Bits Per Second
LED	Light Emitting Diode
Li-Ion	Lithium-Ion
MO	Mobile Originated
MOQ	Minimum Order Quantity
MP	Manufacture Product
MS	Mobile Station (GSM engine)
MT	Mobile Terminated
N.W	Net Weight

PAP	Password Authentication Protocol
PBCCH	Packet Switched Broadcast Control Channel
PCB	Printed Circuit Board
PDU	Protocol Data Unit
PPP	Point-to-Point Protocol
RF	Radio Frequency
RMS	Root Mean Square (value)
RTC	Real Time Clock
RX	Receive Direction
SIM	Subscriber Identification Module
SMS	Short Message Service
TDMA	Time Division Multiple Access
TE	Terminal Equipment
TX	Transmitting Direction
UART	Universal Asynchronous Receiver & Transmitter
URC	Unsolicited Result Code
USSD	Unstructured Supplementary Service Data
VSWR	Voltage Standing Wave Ratio
Vmax	Maximum Voltage Value
Vnorm	Normal Voltage Value
Vmin	Minimum Voltage Value
VIHmax	Maximum Input High Level Voltage Value
VIHmin	Minimum Input High Level Voltage Value
VILmax	Maximum Input Low Level Voltage Value
VILmin	Minimum Input Low Level Voltage Value

VImax	Absolute Maximum Input Voltage Value
VImin	Absolute Minimum Input Voltage Value
VOHmax	Maximum Output High Level Voltage Value
VOHmin	Minimum Output High Level Voltage Value
VOLmax	Maximum Output Low Level Voltage Value
VOLmin	Minimum Output Low Level Voltage Value

Phonebook Abbreviations

LD	SIM Last Dialing phonebook (list of numbers most recently dialed)
MC	Mobile Equipment list of unanswered MT Calls (missed calls)
ON	SIM (or ME) Own Numbers (MSISDNs) list
RC	Mobile Equipment list of Received Calls
SM	SIM phonebook

9 Appendix B GPRS Coding Scheme

Four coding schemes are used in GPRS protocol. The differences between them are shown in the following table.

Table 38: Description of Different Coding Schemes

Scheme	Code Rate	USF	Pre-coded USF	Radio Block excl.USF and BCS	BCS	Tail	Coded Bits	Punctured Bits	Data Rate Kb/s
CS-1	1/2	3	3	181	40	4	456	0	9.05
CS-2	2/3	3	6	268	16	4	588	132	13.4
CS-3	3/4	3	6	312	16	4	676	220	15.6
CS-4	1	3	12	428	16	-	456	-	21.4

Radio block structure of CS-1, CS-2 and CS-3 is shown as the figure below.

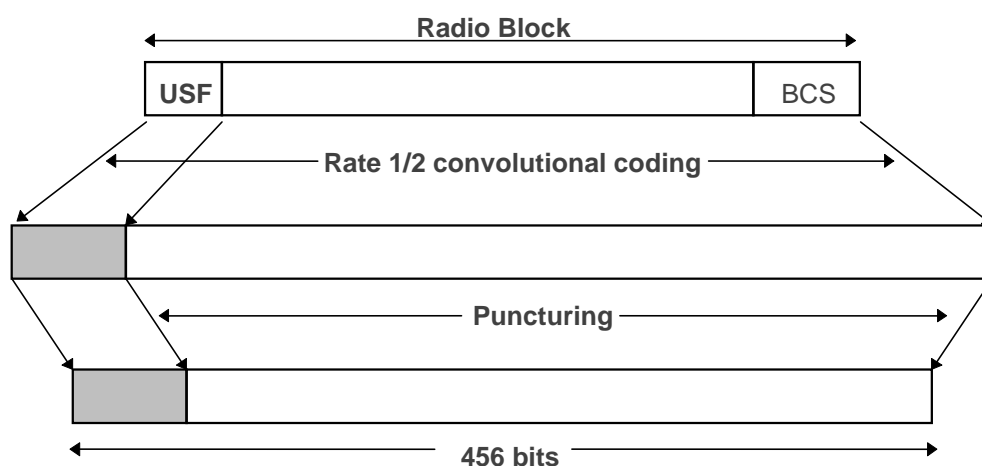


Figure 56: Radio Block Structure of CS-1, CS-2 and CS-3

Radio block structure of CS-4 is shown as the following figure.

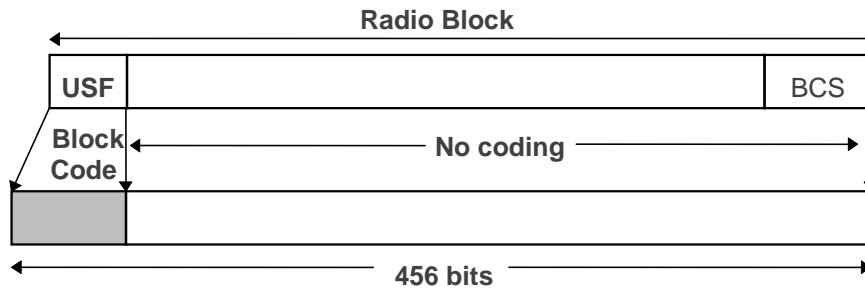


Figure 57: Radio Block Structure of CS-4

10 Appendix C GPRS Multi-slot Class

Twenty-nine classes of GPRS multi-slot modes are defined for MS in GPRS specification. Multi-slot classes are product dependant, and determine the maximum achievable data rates in both the uplink and downlink directions. Written as 3+1 or 2+2, the first number indicates the amount of downlink timeslots, while the second number indicates the amount of uplink timeslots. The active slots determine the total number of slots the GPRS device can use simultaneously for both uplink and downlink communications. The description of different multi-slot classes is shown in the following table.

Table 39: GPRS Multi-slot Classes

Multislot Class	Downlink Slots	Uplink Slots	Active Slots
1	1	1	2
2	2	1	3
3	2	2	3
4	3	1	4
5	2	2	4
6	3	2	4
7	3	3	4
8	4	1	5
9	3	2	5
10	4	2	5
11	4	3	5
12	4	4	5